

Diagonal 6.43 mm (Type 1/2.8) CMOS Solid-state Image Sensor with Square Pixel for Color Cameras

Tentative

IMX415-AAQR-C

STARVIS

Description

The IMX415-AAQR-C is a diagonal 6.4 mm (Type 1/2.8) CMOS active pixel type solid-state image sensor with a square pixel array and 8.42 M effective pixels. This chip operates with analog 2.9 V, digital 1.1 V, and interface 1.8 V triple power supply, and has low power consumption. High sensitivity, low dark current and no smear are achieved through the adoption of R, G and B primary color mosaic filters. This chip features an electronic shutter with variable charge-integration time.

(Applications: Surveillance cameras, FA cameras, Industrial cameras)

Features

- ◆ CMOS active pixel type dots
- ◆ Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆ Input frequency: 24 MHz / 27 MHz / 37.125 MHz / 72 MHz / 74.25 MHz
- ◆ Number of recommended recording pixels: 3840 (H) × 2160 (V) approx. 8.29M pixel
- ◆ Readout mode
 - All-pixel scan mode
 - Horizontal / Vertical 2/2-line binning mode
 - Window cropping mode
 - Horizontal / Vertical direction - Normal / Inverted readout mode
- ◆ Readout rate
 - Maximum frame rate in
 - All-pixel scan mode: 12 bit: 60 frame/s, 10 bit: 90 frame/s (TBD)
- ◆ High dynamic range (HDR) function
 - Multiple exposure HDR
 - Digital overlap HDR
- ◆ Synchronizing sensors function
- ◆ Variable-speed shutter function (resolution 1H units)
- ◆ CDS / PGA function
 - 0 dB to 72 dB (TBD) (step pitch 0.3 dB)
- ◆ Supports I/O
 - CSI-2 serial data output (2 Lane /4 Lane), RAW10 / RAW12 output
- ◆ Recommended exit pupil distance: -30 mm to $-\infty$

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Device Structure

- ◆ CMOS image sensor
- ◆ Image size
 - Type 1/2.8 approx. 8.40 M pixels, All pixels
- ◆ Total number of pixels
 - 3864 (H) × 2228 (V) approx. 8.60 M pixels
- ◆ Number of effective pixels
 - 3864 (H) × 2192 (V) approx. 8.46 M pixels
- ◆ Number of active pixels
 - 3864 (H) × 2176 (V) approx. 8.40 M pixels
- ◆ Number of recommended recording pixels
 - 3840 (H) × 2160 (V) approx. 8.29 M pixels
- ◆ Unit cell size
 - 1.45 μm (H) × 1.45 μm (V)
- ◆ Optical black
 - Horizontal (H) direction: Front 0 pixels, rear 0 pixels
 - Vertical (V) direction: Front 36 pixels, rear 0 pixels
- ◆ Dummy
 - Horizontal (H) direction: Front 0 pixels, rear 0 pixels
 - Vertical (V) direction: Front 1 pixels, rear 1 pixels
- ◆ Substrate material
 - Silicon

Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage (analog : 2.9 V)	AV _{DD}	-0.3	3.3	V	
Supply voltage (interface 1.8 V)	OV _{DD}	-0.3	3.3	V	
Supply voltage (digital : 1.1 V)	DV _{DD}	-0.3	2.0	V	
Input voltage	VI	-0.3	OV _{DD} + 0.3	V	Not exceed 3.3 V
Output voltage	VO	-0.3	OV _{DD} + 0.3	V	Not exceed 3.3 V
Operating temperature	Topr	-30	85	°C	
Storage temperature	Tstg	-40	85	°C	

Application Conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage (analog : 2.9 V)	AV _{DD1}	2.80	2.90	3.00	V
Supply voltage (interface 1.8 V)	OV _{DD}	1.70	1.80	1.90	V
Supply voltage (digital : 1.1 V)	DV _{DD1}	1.00	1.10	1.20	V
Performance guarantee temperature	Tspec	-10	—	60	°C

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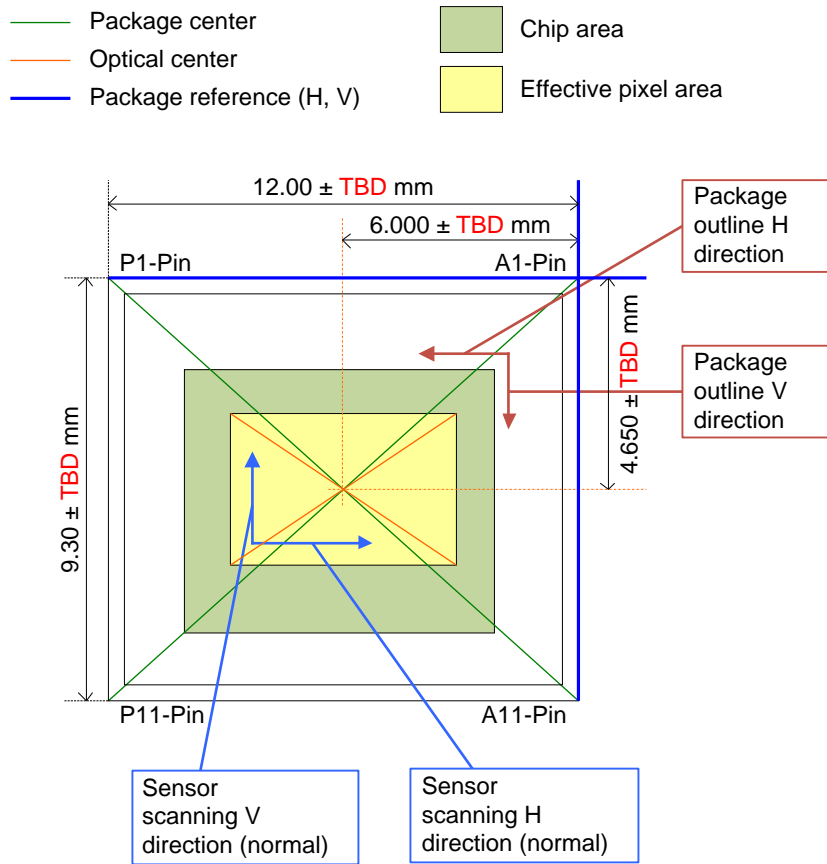
Contents

Description	1
Features	1
Device Structure	2
Absolute Maximum Ratings	3
Application Conditions	3
USE RESTRICTION NOTICE	4
Optical Center	7
Pixel Arrangement	8
Block Diagram and Pin Configuration	9
Pin Description	11
Electrical Characteristics	14
DC Characteristics	14
Current Consumption (Temtative)	15
AC Characteristics	16
Master Clock Waveform (INCK)	16
System Clear (XCLR)	17
XVS / XHS Input Characteristics In Slave Mode (Register XMASTER = 1)	18
XVS / XHS Input Characteristics In Master Mode (Register XMASTER = 0)	18
Serial Communication	19
I/O Equivalent Circuit Diagram	21
Spectral Sensitivity Characteristics	22
Image Sensor Characteristics	23
Image Sensor Characteristics Measurement Method	24
Measurement Conditions	24
Color Coding of Physical Pixel Array	24
Definition of standard imaging conditions	24
Measurement Method	25
Setting Registers Using Serial Communication	26
Description of Setting Registers (I ² C)	26
Register Communication Timing (I ² C)	27
Communication Protocol	28
Register Write and Read (I ² C)	29
Single Read from Random Location	29
Single Read from Current Location	29
Sequential Read Starting from Random Location	30
Sequential Read Starting from Current Location	30
Single Write to Random Location	31
Sequential Write Starting from Random Location	31
Register Map	32
Readout Drive mode	46
Operating mode	46
Image Data Output Format (CSI-2 output)	48
Frame Format	48
Frame Structure	48
Embedded Data Line	49
Image Data Output Format	51
All-pixel mode	51
Horizontal/Vertical 2/2-line binning mode	54
Window Cropping Mode	57
Description of Various Function	59
Standby Mode	59
Slave Mode and Master Mode	60
Gain Adjustment Function	62
Black Level Adjustment Function	63
Normal Operation and Inverted Operation	64
Shutter and Integration Time Settings	65
Example of Integration Time Setting	65
Normal Exposure Operation (Controlling the Integration Time in 1H Units)	66

Long Exposure Operation (Control by Expanding the Number of Lines per Frame).....	67
Example of Integration Time Settings	68
Signal Output	69
CSI-2 output.....	69
MIPI Transmitter	71
Number of Internal A/D Conversion Bits Setting.....	72
Output Signal Range	72
INCK Setting.....	73
Register Hold Setting.....	76
Mode Transitions	77
Other Function.....	78
Power-on and Power-off Sequence.....	79
Power-on sequence.....	79
Slew Rate Limitation of Power-on Sequence.....	80
Power-off sequence.....	81
Sensor Setting Flow.....	82
Setting Flow in Sensor Slave Mode	82
Setting Flow in Sensor Master Mode	83
Peripheral Circuit.....	84
Spot Pixel Specifications	85
Zone Definition.....	85
Notice on White Pixels Specifications	86
Measurement Method for Spot Pixels	87
Spot Pixel Pattern Specification	88
Marking	89
Notes On Handling.....	90
Package Outline	92
List of Trademark Logos and Definition Statements	93
Revision History	94

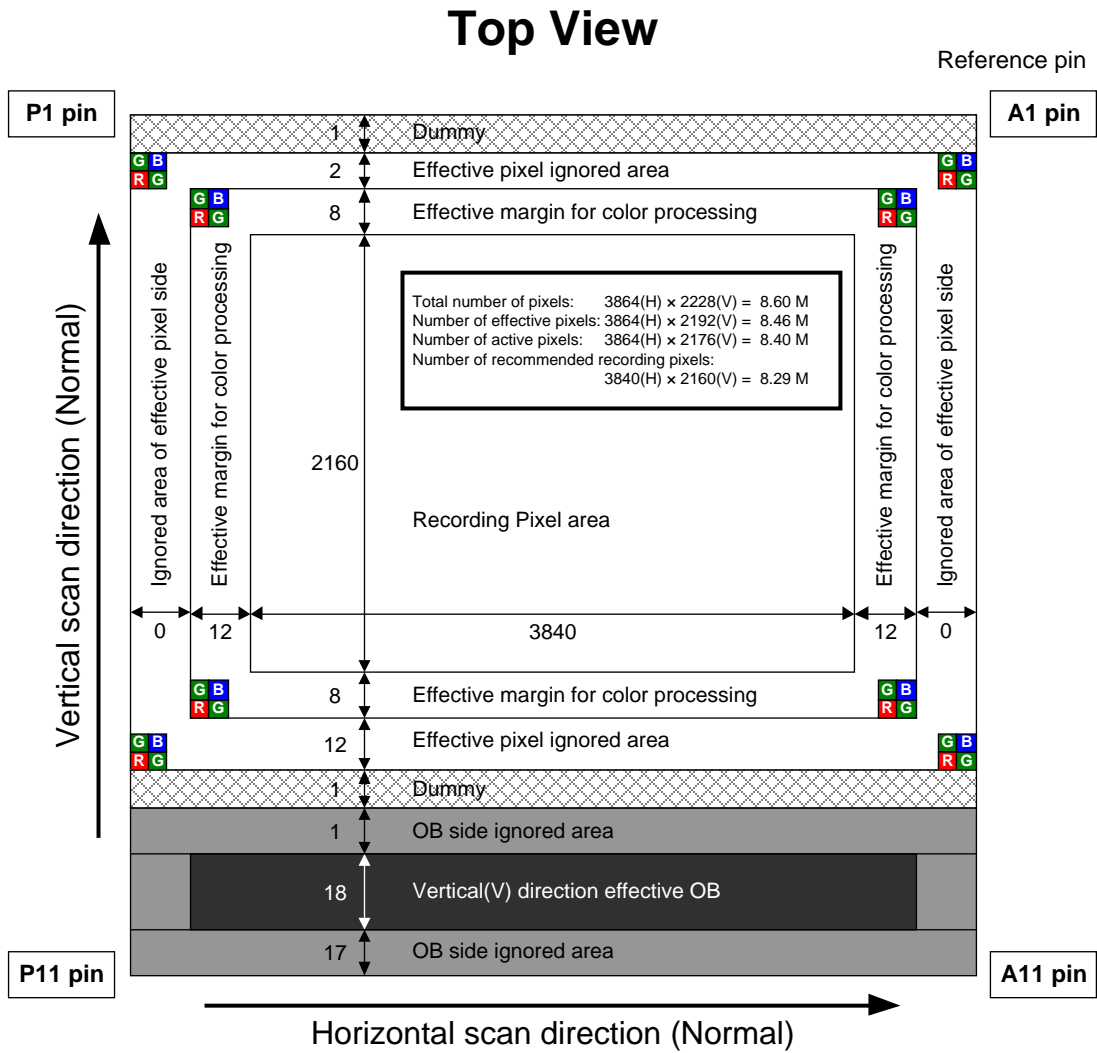
Optical Center

Top View



Optical Center

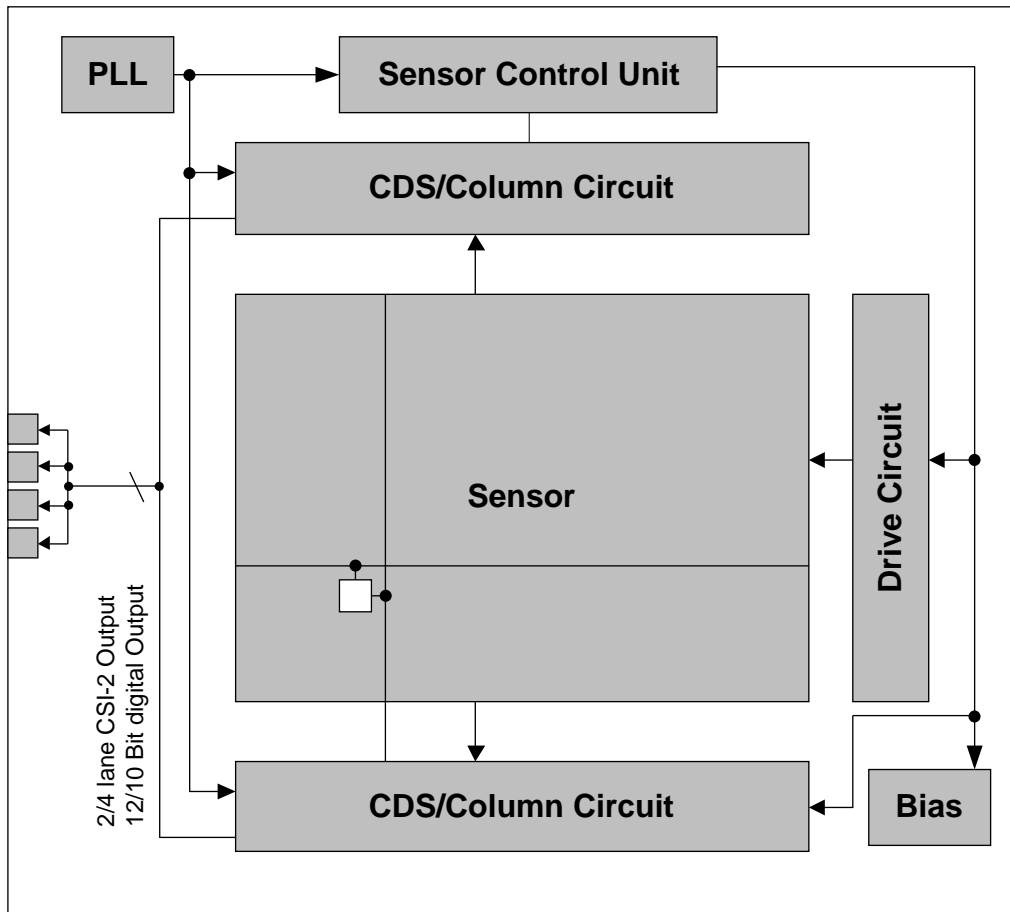
Pixel Arrangement



- * Reference pin number is consecutive numbering of package pin array. See the Pin Configuration for the number of each pin.
- ** Dummy is the effective pixels to ignore the data content.

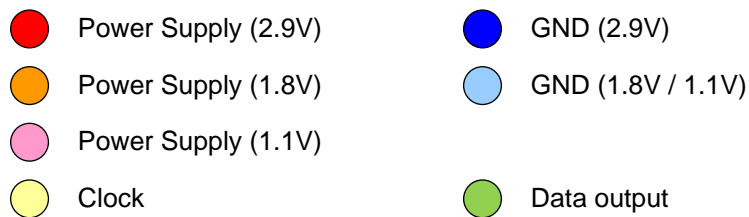
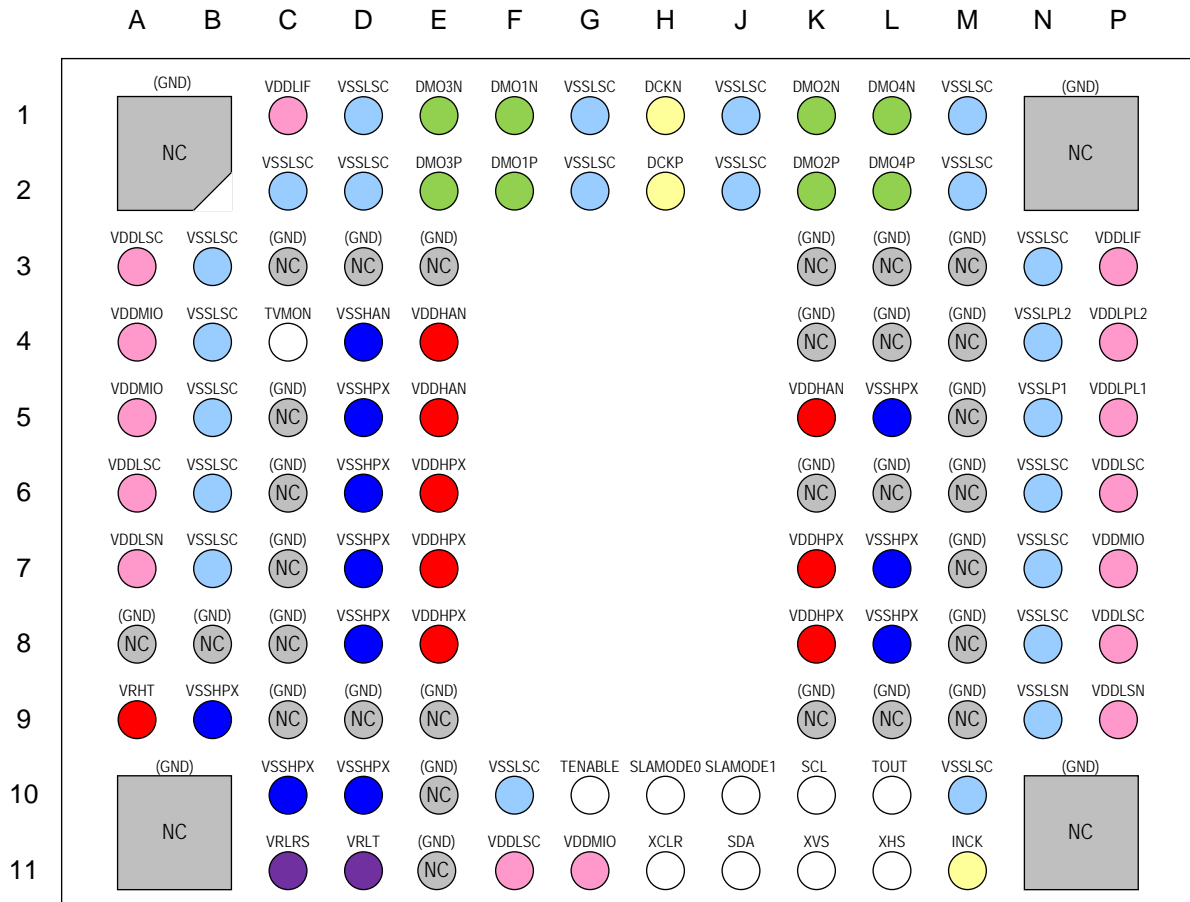
Pixel Arrangement (Top View)

Block Diagram and Pin Configuration



Block Diagram

Bottom View



*The N.C. pin with (GND) can be connected to GND.

Pin Configuration (Bottom View)

Pin Description

No.	Pin No	I/O	Analog / Digital	Symbol	Description
1	A1	—	—	N.C.	GND connectable
2	A3	Power	D	VDDLSC	1.1 V power supply
3	A4	Power	D	VDDMIO	1.8 V power supply
4	A5	Power	D	VDDMIO	1.8 V power supply
5	A6	Power	D	VDDLSC	1.1 V power supply
6	A7	Power	D	VDDLSC	1.1 V power supply
7	A8	—	—	N.C.	GND connectable
8	A9	O	A	VRHT	Capacitor connection
9	A11	—	—	N.C.	GND connectable
10	B3	GND	D	VSSLSC	1.1V GND
11	B4	GND	D	VSSLSC	1.1V GND
12	B5	GND	D	VSSLSC	1.1V GND
13	B6	GND	D	VSSLSC	1.1V GND
14	B7	GND	D	VSSLCN	1.1V GND
15	B8	—	—	N.C.	GND connectable
16	B9	GND	A	VSSHPX	2.9V GND
17	C1	Power	D	VDDLIF	1.1 V power supply
18	C2	GND	D	VSSLSC	1.1V GND
19	C3	—	—	N.C.	GND connectable
20	C4	O	A	TVMON	TEST output pin, OPEN
21	C5	—	—	N.C.	GND connectable
22	C6	—	—	N.C.	GND connectable
23	C7	—	—	N.C.	GND connectable
24	C8	—	—	N.C.	GND connectable
25	C9	—	—	N.C.	GND connectable
26	C10	GND	A	VSSHPX	2.9V GND
27	C11	O	A	VRLRS	Capacitor connection
28	D1	GND	D	VSSLSC	1.1V GND
29	D2	GND	D	VSSLSC	1.1V GND
30	D3	—	—	N.C.	GND connectable
31	D4	GND	A	VSSHAN	2.9V GND
32	D5	GND	A	VSSHPX	2.9V GND
33	D6	GND	A	VSSHPX	2.9V GND
34	D7	GND	A	VSSHPX	2.9V GND
35	D8	GND	A	VSSHPX	2.9V GND
36	D9	—	—	N.C.	GND connectable
37	D10	GND	A	VSSHPX	2.9V GND
38	D11	O	A	VRLT	Capacitor connection
39	E1	O	D	DMO3N	CSI-2 output (data)
40	E2	O	D	DMO3P	CSI-2 output (data)
41	E3	—	—	N.C.	GND connectable
42	E4	Power	A	VDDHAN	2.9 V power supply
43	E5	Power	A	VDDHAN	2.9 V power supply
44	E6	Power	A	VDDHPX	2.9 V power supply
45	E7	Power	A	VDDHPX	2.9 V power supply
46	E8	Power	A	VDDHPX	2.9 V power supply

No.	Pin No	I/O	Analog / Digital	Symbol	Description
47	E9	—	—	N.C.	GND connectable
48	E10	—	—	N.C.	GND connectable
49	E11	—	—	N.C.	GND connectable
50	F1	O	D	DMO1N	CSI-2 output (data)
51	F2	O	D	DMO1P	CSI-2 output (data)
52	F10	GND	D	VSSLSC	1.1V GND
53	F11	Power	D	VDDLSC	1.1 V power supply
54	G1	GND	D	VSSLSC	1.1V GND
55	G2	GND	D	VSSLSC	1.1V GND
56	G10	I	D	TENABLE	Test enable, OPEN
57	G11	Power	D	VDDMIO	1.8 V power supply
58	H1	O	D	DCKN	CSI-2 output (clock)
59	H2	O	D	DCKP	CSI-2 output (clock)
60	H10	I	D	SLAMODE0	Select slave address
61	H11	I	D	XCLR	System clear
62	J1	GND	D	VSSLSC	1.1V GND
63	J2	GND	D	VSSLSC	1.1V GND
64	J10	I	D	SLAMODE1	Select slave address
65	J11	I/O	D	SDA	Serial data communication
66	K1	O	D	DMO2N	CSI-2 output (data)
67	K2	O	—	DMO2P	CSI-2 output (data)
68	K3	—	—	N.C.	GND connectable
69	K4	—	—	N.C.	GND connectable
70	K5	Power	A	VDDHAN	2.9 V power supply
71	K6	—	—	N.C.	GND connectable
72	K7	Power	A	VDDHPX	2.9 V power supply
73	K8	Power	A	VDDHPX	2.9 V power supply
74	K9	—	—	N.C.	GND connectable
75	K10	I/O	D	SCL	Serial clock input
76	K11	I/O	D	XVS	Vertical sync signal
77	L1	O	D	DMO4N	CSI-2 output (data)
78	L2	O	D	DMO4P	CSI-2 output (data)
79	L3	—	—	N.C.	GND connectable
80	L4	—	—	N.C.	GND connectable
81	L5	GND	A	VSSHPX	2.9V GND
82	L6	—	—	N.C.	GND connectable
83	L7	GND	A	VSSHPX	2.9V GND
84	L8	GND	A	VSSHPX	2.9V GND
85	L9	—	—	N.C.	GND connectable
86	L10	I/O	D	TOUT	Digital TEST output pin, OPEN
87	L11	I/O	D	XHS	Horizontal sync signal
88	M1	GND	D	VSSLSC	1.1V GND
89	M2	GND	D	VSSLSC	1.1V GND
90	M3	—	—	N.C.	GND connectable
91	M4	—	—	N.C.	GND connectable
92	M5	—	—	N.C.	GND connectable
93	M6	—	—	N.C.	GND connectable
94	M7	—	—	N.C.	GND connectable
95	M8	—	—	N.C.	GND connectable

No.	Pin No	I/O	Analog / Digital	Symbol	Description
96	M9	—	—	N.C.	GND connectable
97	M10	GND	D	VSSLSC	1.1V GND
98	M11	I	D	INCK	Master clock input
99	N3	GND	D	VSSLSC	1.1V GND
100	N4	GND	A	VSSLPL2	1.1V GND
101	N5	GND	A	VSSLPL1	1.1V GND
102	N6	GND	D	VSSLSC	1.1V GND
103	N7	GND	D	VSSLSC	1.1V GND
104	N8	GND	D	VSSLSC	1.1V GND
105	N9	GND	D	VSSLCN	1.1V GND
106	P1	—	—	N.C.	GND connectable
107	P3	Power	D	VDDLIF	1.1 V power supply
108	P4	Power	A	VDDLPL2	1.1 V power supply
109	P5	Power	A	VDDLPL1	1.1 V power supply
110	P6	Power	D	VDDLSC	1.1 V power supply
111	P7	Power	D	VDDMIO	1.1 V power supply
112	P8	Power	D	VDDLSC	1.1 V power supply
113	P9	Power	D	VDDLCN	1.1 V power supply
114	P11	—	—	N.C.	GND connectable

Electrical Characteristics

DC Characteristics

Item	Pins	Symbol	Condition	Min.	Typ.	Max.	Unit
Supply voltage	Analog	VDDHx	AV_{DD}	2.80	2.90	3.00	V
	Interface	VDDMx	OV_{DD}	1.70	1.80	1.90	V
	Digital	VDDLx	DV_{DD}	1.00	1.10	1.20	V
Digital input voltage	XHS XVS XCLR INCK SLAMODE0 SLAMODE1 SDA SCL	VIH	XVS / XHS Slave Mode	$0.8 \times OV_{DD}$	—	—	V
		VIL		—	—	$0.2 \times OV_{DD}$	V
Digital output voltage	XHS XVS TOUT	VOH	XVS / XHS Master Mode	$OV_{DD} - 0.2$	—	—	V
		VOL		—	—	0.2	V

Current Consumption (Temptative)

Item	Symbol	Typ.	Max.	Unit
Operating current MIPI CSI-2 / 4 Lane, 2079 Mbps 12 bit, 60 frame/s All-pixel mode	I _{AVDD}	TBD	1.38 (TBD)	mA
	I _{OVDD}	TBD	1.0 (TBD)	mA
	I _{DVDD}	TBD	280 (TBD)	mA
Standby current	I _{AVDD_STB}	—	TBD	mA
	I _{OVDD_STB}	—	TBD	mA
	I _{DVDD_STB}	—	TBD	mA

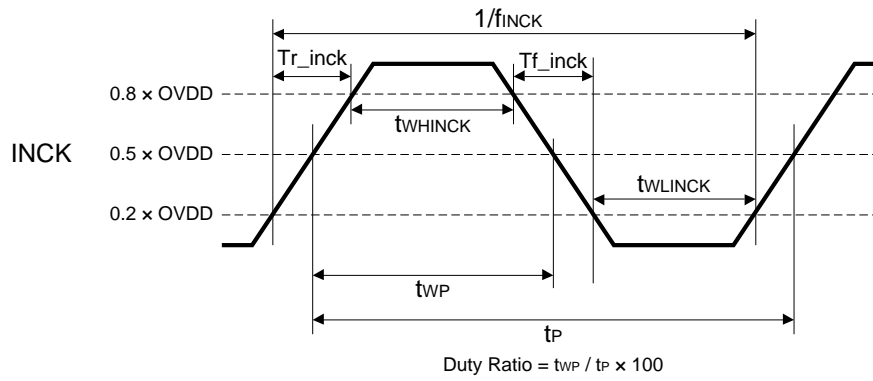
Operating current: (Typ.) Supply voltage 2.9 V / 1.8 V / 1.1 V, T_j = 25 °C, standard luminous intensity.
 (Max.) Supply voltage 3.0 V / 1.9 V / 1.2 V, T_j = 60 °C, worst state of internal circuit operating current consumption,

Standby: (Max.) Supply voltage 3.0 V / 1.9 V / 1.2 V, T_j = 60 °C, INCK: 0 V, light-obstructed state.

(Note) These current values are reference values for PCB design.

AC Characteristics

Master Clock Waveform (INCK)

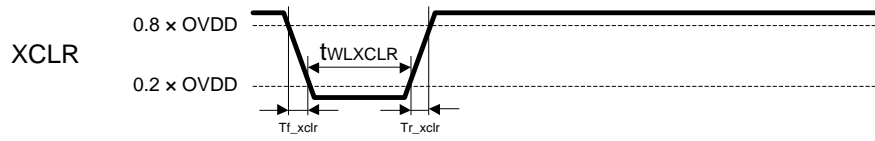


INCK 24MHz, 27MHz, 37.125MHz, 72MHz, 74.25MHz

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
INCK clock frequency	f_{INCK}	$f_{INCK} \times 0.96$	f_{INCK}	$f_{INCK} \times 1.02$	MHz	$f_{INCK} = 24 \text{ MHz}, 27 \text{ MHz}, 37.125 \text{ MHz}, 72 \text{ MHz}, 74.25 \text{ MHz}$
INCK Low level pulse width	t_{WLINCK}	4	—	—	ns	
INCK High level pulse width	t_{WHINCK}	4	—	—	ns	
INCK clock duty	—	45	50	55	%	Define with $0.5 \times OV_{DD}$
INCK Rise time	Tr_inck	—	—	5	ns	20 % to 80 %
INCK Fall time	Tf_inck	—	—	5	ns	80 % to 20 %

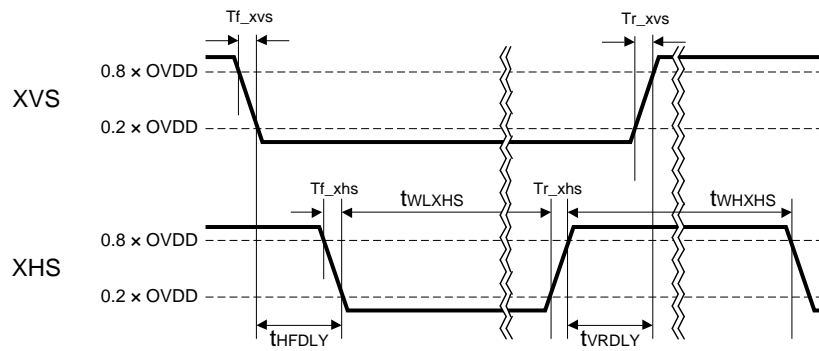
* The INCK fluctuation affects the frame rate.

System Clear (XCLR)



Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
XCLR Low level pulse width	t_{WLXCLR}	$4 / f_{INCK}$	—	—	ns	
XCLR Rise time	Tr_xclr	—	—	5	ns	20 % ~80 %
XCLR Fall time	Tf_xclr	—	—	5	ns	80 % ~20 %

XVS / XHS Input Characteristics In Slave Mode (Register XMASTER = 1)



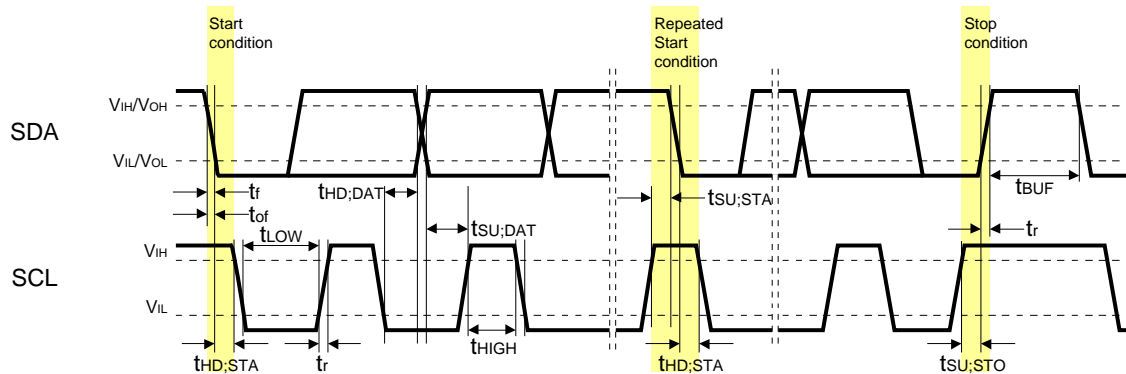
Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
XHS Low level pulse width	t_{WDXHS}	$4 / f_{INCK}$	—	—	ns	
XHS High level pulse width	t_{WHXHS}	$4 / f_{INCK}$	—	—	ns	
XVS - XHS fall width	t_{HFDLY}	$1 / f_{INCK}$	—	—	ns	
XHS - XVS rise width	t_{VRDLY}	$1 / f_{INCK}$	—	—	ns	
XVS Rise time	Tr_xvs	—	—	5	ns	20 % to 80 %
XVS Fall time	Tf_xvs	—	—	5	ns	80 % to 20 %
XHS Rise time	Tr_xhs	—	—	5	ns	20 % to 80 %
XHS Fall time	Tf_xhs	—	—	5	ns	80 % to 20 %

XVS / XHS Input Characteristics In Master Mode (Register XMASTER = 0)

* XVS and XHS cannot be used for the sync signal to pixels.
 Be sure to detect sync code to detect the start of effective pixels in 1 line.
 For the output waveforms in master mode, see the item of “Slave Mode and Master Mode”

Serial Communication

I²C



I²C Specification

Item	Symbol	Min.	Typ.	Max.	Unit	
Low level input voltage	V _{IL}	-0.3	—	0.3 × OV _{DD}	V	
High level input voltage	V _{IH}	0.7 × OV _{DD}	—	1.9	V	
Low level output voltage	V _{OL}	0	—	0.2 × OV _{DD}	V	OV _{DD} < 2 V, Sink 3 mA
High level output voltage	V _{OH}	0.8 × OV _{DD}	—	—	V	
Input current	I _i	-10	—	10	μA	0.1 × OV _{DD} - 0.9 × 0 Remarks V _{DD}
Input Capacitance for SCL / SDA	C _i	—	—	10	pF	

I²C AC Characteristics (Standard mode, Fast mode)

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
SCL clock frequency	f _{SCL}	0	—	400	kHz	
Hold time (Start Condition)	t _{HD;STA}	0.6	—	—	μs	
Low period of the SCL clock	t _{LOW}	1.3	—	—	μs	
High period of the SCL clock	t _{HIGH}	0.6	—	—	μs	
Set-up time (Repeated Start Condition)	t _{SU;STA}	0.6	—	—	μs	
Data hold time	t _{HD;DAT}	0	—	0.9	μs	
Data set-up time	t _{SU;DAT}	100	—	—	ns	
Rise time of both SDA and SCL signals	t _r	—	—	300	ns	
Fall time of both SDA and SCL signals	t _f	—	—	300	ns	
Set-up time (Stop Condition)	t _{SU;STO}	0.6	—	—	μs	
Bus free time between a STOP and START Condition	t _{BUF}	1.3	—	—	μs	
Output fall time	t _{of}	—	—	250	ns	Load 10 pF to 400 pF, 0.7 × OV _{DD} to 0.3 × OV _{DD}

I²C AC Characteristics (Fast mode +)

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
SCL clock frequency	f _{SCL}	0	—	1000	kHz	INCK ≥ 16 MHz
Hold time (Start Condition)	t _{HD;STA}	0.26	—	—	μs	
Low period of the SCL clock	t _{LOW}	0.5	—	—	μs	
High period of the SCL clock	t _{HIGH}	0.26	—	—	μs	
Set-up time (Repeated Start Condition)	t _{SU;STA}	0.26	—	—	μs	
Data hold time	t _{HD;DAT}	0	—	0.9	μs	
Data set-up time	t _{SU;DAT}	50	—	—	ns	
Rise time of both SDA and SCL signals	t _r	—	—	120	ns	
Fall time of both SDA and SCL signals	t _f	—	—	120	ns	
Set-up time (Stop Condition)	t _{SU;STO}	0.26	—	—	μs	
Bus free time between a STOP and START Condition	t _{BUF}	0.5	—	—	μs	
Output fall time	t _{of}	—	—	120	ns	Load 10 pF to 400 pF, 0.7 × OV _{DD} to 0.3 × OV _{DD}

I/O Equivalent Circuit Diagram

□: External pin

Symbol	Equivalent circuit	Symbol	Equivalent circuit
TENABLE		XVS XHS TOUT	
INCK		XCLR SLAMODE1 SLAMODE2	
SDA SCL		VRLRS VRLT	
TVMON		DMOPx DMOMx DMCKP DMCKM	
VRHT			

Spectral Sensitivity Characteristics

(Characteristics in the wafer status)

T.B.D.

Image Sensor Characteristics

(AV_{DD} = 2.9 V, OV_{DD} = 1.8 V, DV_{DD} = 1.1 V, T_j = 60 °C, All-pixel mode, 12 bit 30 frame/s, Gain: 0 dB)

Item	Symbol	Min.	Typ.	Max.	Unit	Measurement method	Remarks
G sensitivity	S	TBD (TBD)	TBD (TBD)	—	Digit (mV)	1	1/30 s storage 12 bit converted value
Sensitivity ratio	R / G	RG	—	TBD	—	2	—
	B / G	BG	—	TBD	—		
Saturation signal	Vsat	TBD (TBD)	—	—	Digit (mV)	3	12 bit converted value
Video signal shading	SH	—	—	TBD	%	4	—
Vertical line	VL	—	—	TBD	μV	5	12 bit converted value'
Dark signal	Vdt	—	—	TBD (TBD)	Digit (mV)	6	1/30 s storage 12 bit converted value
Dark signal shading	ΔVdt	—	—	TBD (TBD)	Digit (mV)	7	1/30 s storage 12 bit converted value

- Note)
1. Converted value into mV using 1Digit = TBD mV for 12-bit output and 1Digit = TBD mV for 10-bit output.
 2. The video signal shading is the measured value in the wafer status (including color filter) and does not include characteristics of the seal glass.
 3. The characteristics above apply to effective pixel area.

Image Sensor Characteristics Measurement Method

Measurement Conditions

1. In the following measurements, the device drive conditions are at the typical values of the bias conditions and clock voltage conditions.
2. In the following measurements, spot pixels are excluded and, unless otherwise specified, the optical black (OB) level is used as the reference for the signal output, which is taken as the value of the Gr / Gb channel signal output or the R / B channel signal output of the measurement system.

Color Coding of Physical Pixel Array

The primary color filters of this image sensor are arranged in the layout shown in the figure below. Gr and Gb represent the G signal on the same line as the R and B signals, respectively. The Gb signal and B signal lines and the R signal and Gr signal lines are output successively.

Gb	B	Gb	B
R	Gr	R	Gr
Gb	B	Gb	B
R	Gr	R	Gr

Color Coding Diagram

Definition of standard imaging conditions

- ◆ Standard imaging condition I:
Use a pattern box (luminance: 706 cd/m², color temperature of 3200 K halogen source) as a subject. (Pattern for evaluation is not applicable.) Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter and image at F5.6. The luminous intensity to the sensor receiving surface at this point is defined as the standard sensitivity testing luminous intensity.
- ◆ Standard imaging condition II:
Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.
- ◆ Standard imaging condition III:
Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens (exit pupil distance - 30 mm) with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

Measurement Method

1. Sensitivity
Set the measurement condition to the standard imaging condition I. After setting the electronic shutter mode with a shutter speed of 1/100 s, measure the Gr and Gb signal outputs (VGr, VGb) at the center of the screen, and substitute the values into the following formula.

$$S = (VGr + VGb) / 2 \times 100 / 30 \text{ [mV]}$$

2. Sensitivity ratio
Set the measurement condition to the standard imaging condition II. After adjusting the average value of the Gr and Gb signal outputs to TBD mV, measure the R signal output (VR [mV]), the Gr and Gb signal outputs (VGr, VGb [mV]) and the B signal output (VB [mV]) at the center of the screen in frame readout mode, and substitute the values into the following formulas.

$$VG = (VGr + VGb) / 2$$

$$RG = VR / VG$$

$$BG = VB / VG$$

3. Saturation signal
Set the measurement condition to the standard imaging condition II. After adjusting the luminous intensity to 20 times the intensity with the average value of the Gr and Gb signal outputs, TBD mV, measure the average values of the Gr, Gb, R and B signal outputs.
4. Video signal shading
Set the measurement condition to the standard imaging condition III. With the lens diaphragm at F2.8, adjust the luminous intensity so that the average value of the Gr and Gb signal outputs is TBD mV. Then measure the maximum value (Gmax [mV]) and the minimum value (Gmin [mV]) of the Gr and Gb signal outputs, and substitute the values into the following formula.

$$SH = (Gmax - Gmin) / TBD \times 100 \text{ [%]}$$

5. Vertical Line
With the device junction temperature of 60 °C and the device in the light-obstructed state, calculates each average output of Gr, Gb, R and B on respective columns. Calculates maximum value of difference with adjacent column on the same color (VL [μV]).
6. Dark signal
With the device junction temperature of 60 °C and the device in the light-obstructed state, divide the output difference between 1/30 s integration and 1/300 s integration by 0.9, and calculate the signal output converted to 1/30 s integration. Measure the average value of this output (Vdt [mV]).
7. Dark signal shading
After the measurement item 6, measure the maximum value (Vdmax [mV]) and the minimum value (Vdmin [mV]) of the dark signal output, and substitute the values into the following formula.

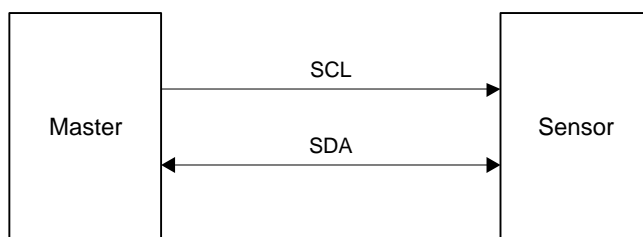
$$\Delta Vdt = Vdmax - Vdmin \text{ [mV]}$$

Setting Registers Using Serial Communication

This sensor can write and read the setting values of the various registers shown in the Register Map by I²C communication. See the Register Map for the addresses and setting values to be set.

Description of Setting Registers (I²C)

The serial data input order is MSB-first transfer. The table below shows the various data types and descriptions. Using SLAMODE0 and SLAMODE1 pins, SLAVE address can be changed.



Pin connection of serial communication

SLAVE Address

SLAMODE1 pin	SLAMODE0 pin	MSB							LSB
Low	Low	0	0	1	1	0	1	0	R / W
Low	High	0	0	1	0	0	0	0	R / W
High	Low	0	1	1	0	1	1	0	R / W
High	High	0	1	1	0	1	1	1	R / W

* R/W is data direction bit

R / W

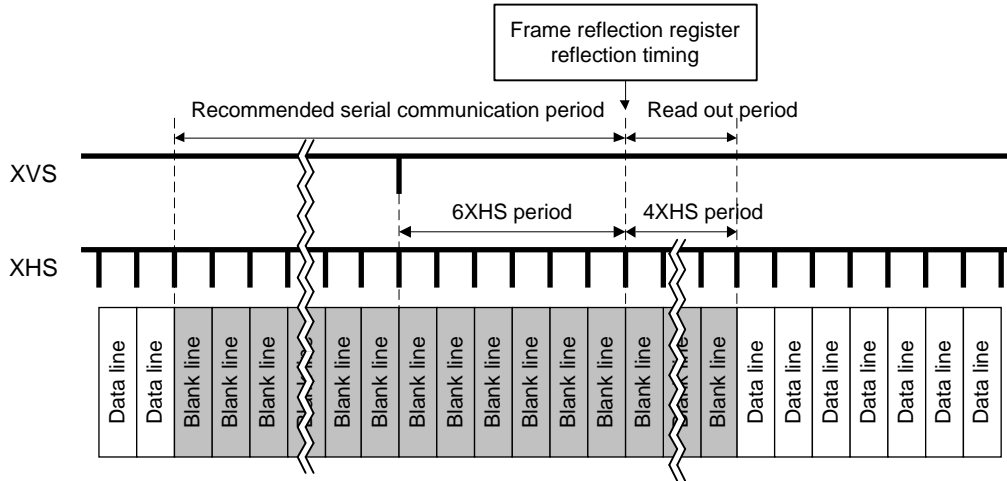
R / W bit	Data direction
0	Write (Master to Sensor)
1	Read (Sensor to Master)

I²C pin description

Symbol	Pin No.	Remarks
SCL	K10	I ² C serial clock input
SDA	J11	I ² C serial data communication

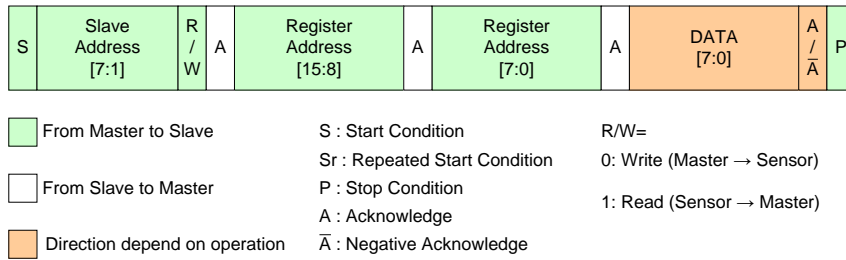
Register Communication Timing (I²C)

In I²C communication system, communication can be performed during the falling edge of XVS to 6H. For the registers marked "V" in the item of Reflection timing, when the communication is performed in the communication period shown in the figure below they are reflected by frame reflection timing. For the registers noted "Immediately" in the item of Reflection timing, the settings are reflected when the communication is performed. (For the immediate reflection registers other than STANDBY, REGHOLD, XMSTA, SW_RESET, XVSOUTSEL [1:0] and XHSOUTSEL [1:0], set them in sensor standby state.) Using REGHOLD function is recommended for register setting using I²C communication. For REGHOLD function, see "Register Transmission Setting" in "Description of Functions".



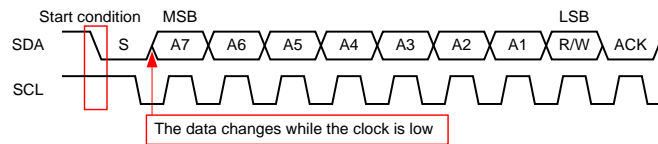
Communication Protocol

I²C serial communication supports a 16-bit register address and 8-bit data message type.

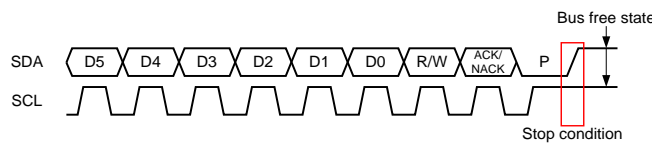


Communication Protocol

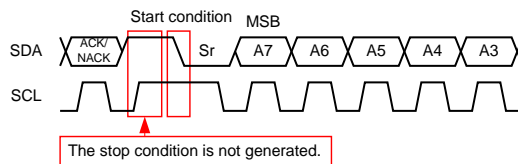
Data is transferred serially, MSB first in 8-bit units. After each data byte is transferred, A (Acknowledge) / \bar{A} (Negative Acknowledge) is transferred. Data (SDA) is transferred at the clock (SDL) cycle. SDA can change only while SCL is Low, so the SDA value must be held while SCL is High. The Start condition is defined by SDA changing from High to Low while SCL is High. When the Stop condition is not generated in the previous communication phase and Start condition for the next communication is generated, that Start condition is recognized as a Repeated Start condition.



Start Condition

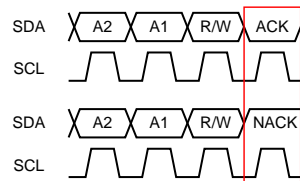


Stop Condition



Repeated Start Condition

After transfer of each data byte, the Master or the sensor transmits an Acknowledge / Negative Acknowledge and release (does not drive) SDA. When Negative Acknowledge is generated, the Master must immediately generate the Stop Condition and end the communication.



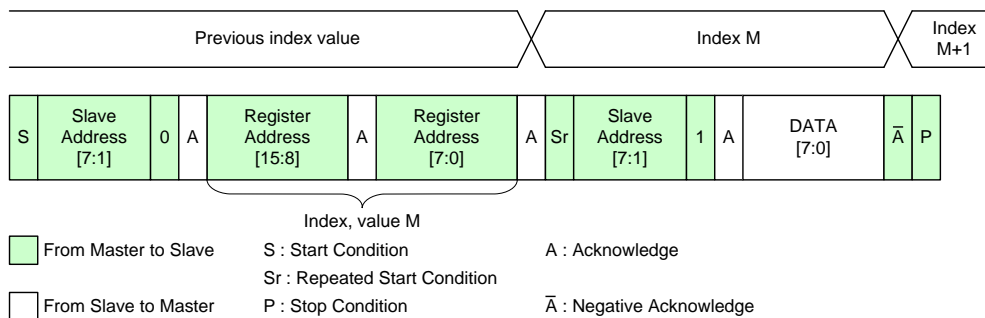
Acknowledge and Negative Acknowledge

Register Write and Read (I²C)

This sensor corresponds to four read modes and the two write modes.

Single Read from Random Location

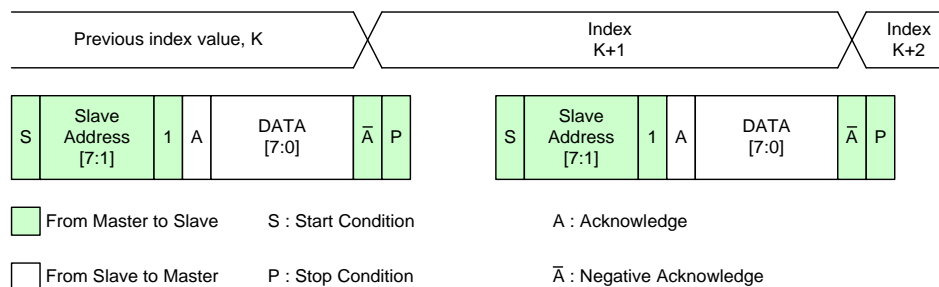
The sensor has an index function that indicates which address it is focusing on. In reading the data at an optional single address, the Master must set the index value to the address to be read. For this purpose it performs dummy write operation up to the register address. The upper level of the figure below shows the sensor internal index value, and the lower level of the figure shows the SDA I/O data flow. The Master sets the sensor index value to M by designating the sensor slave address with a write request, then designating the address (M). Then, the Master generates the start condition. The Start Condition is generated without generating the Stop Condition, so it becomes the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge immediately followed by the index address data on SDA. After the Master receives the data, it generates a Negative Acknowledge and the Stop Condition to end the communication



Single Read from Random Location

Single Read from Current Location

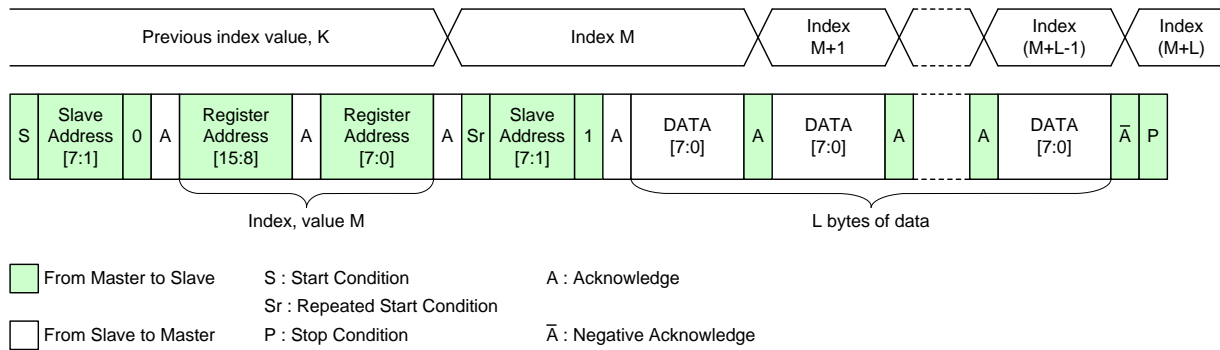
After the slave address is transmitted by a write request, that address is designated by the next communication and the index holds that value. In addition, when data read/write is performed, the index is incremented by the subsequent Acknowledge/Negative Acknowledge timing. When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after Acknowledge. After receiving the data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication, but the index value is incremented, so the data at the next address can be read by sending the slave address with a read request.



Single Read from Current Location

Sequential Read Starting from Random Location

In reading data sequentially, which is starting from an optional address, the Master must set the index value to the start of the addresses to be read. For this purpose, dummy write operation includes the register address setting. The Master sets the sensor index value to M by designating the sensor slave address with a read request, then designating the address (M). Then, the Master generates the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge followed immediately by the index address data on SDA. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.

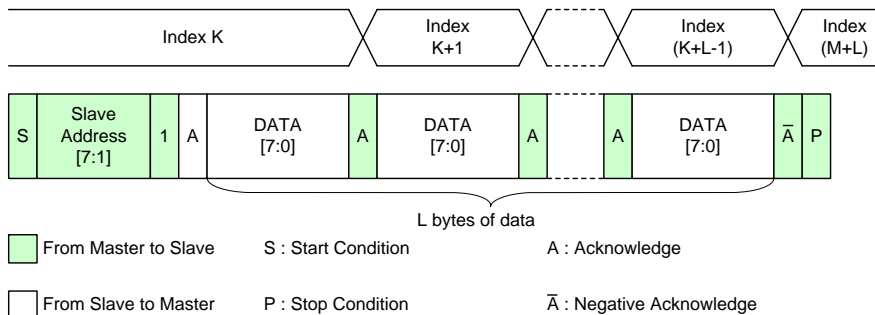


Sequential Read Starting from Random Location

Sequential Read Starting from Current Location

When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after the Acknowledge. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA.

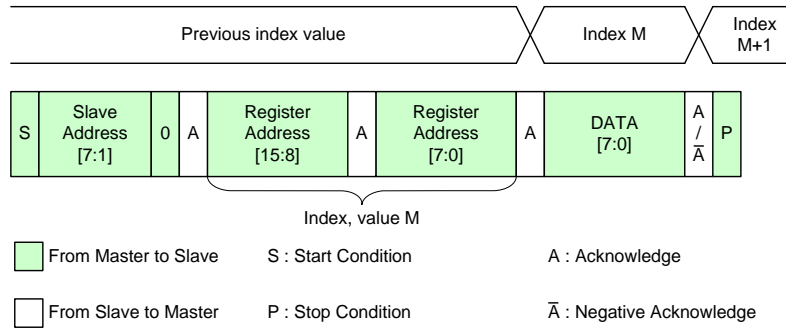
This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



Sequential Read Starting from Current Location

Single Write to Random Location

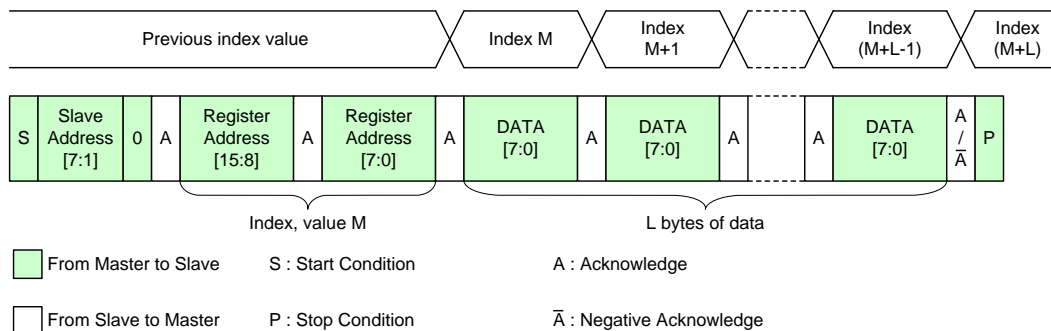
The Master sets the sensor index value to M by designating the sensor slave address with a write request, and designating the address (M). After that the Master can write the value in the designated register by transmitting the data to be written. After writing the necessary data, the Master generates the Stop Condition to end the communication.



Single Write to Random Location

Sequential Write Starting from Random Location

The Master can write a value to register address M by designating the sensor slave address with a write request, designating the address (M), and then transmitting the data to be written. After the sensor receives the write data, it outputs an Acknowledge and at the same time increments the register address, so the Master can write to the next address simply by continuing to transmit data. After the Master writes the necessary number of bytes, it generates the Stop Condition to end the communication.



Sequential Write Starting from Random Location

Register Map

This sensor has a total of 4352 bytes (256×17) of registers, composed of registers with LSB addresses 00h to FFh that correspond to MSB address 30h to 40h. Use the initial values for empty address. Some registers must be change from the initial values, so the sensor control side should be capable of setting 4352 bytes.

There are three different register reflection timings.

About the Reflection timing column of the Register Map, registers noted as "I" are reflected immediately after writing to register, registers noted as "S" are set during standby mode and reflected after standby canceled, registers noted as "V" are reflected at "Fame reflection register reflection timing" on the figure described in the section of "Setting Registers with Serial Communication".

Do not perform communication to addresses not listed in the Register Map. Doing so may result in operation errors. However, other registers that requires communication to address not listed above may be added, so addresses up to FFh should be supported for LSB address; 3000h to 40FFh.

- * For the register that is writing " * " to the setting value in description (Indicated by red letter), change the value from the default value after the reset.
- ** In Gain setting only, it is reflected on the next frame which was settings.
- *** Setting except for the setting values described in the description column is prohibited.

(1) Registers corresponding to address = 30**h.

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3000h	0	STANDBY	Standby 0: Operating 1: Standby	1h	01h	I
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3001h	0	REGHOLD	Register hold (Function not to update V reflection register) 0: Invalid 1: Valid	0h	00h	I
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3002h	0	XMSTA	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop	1h	01h	I
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3003h	0	XMASTER	Select Master /Slave mode 0: Master mode 1: Master mode	0h	0h	S
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—

Address	bit	Register name	Description	Default value after reset		Reflection timing	
				By register	By address		
3008h	0	BCWAIT_TIME [9:0]	LSB	0FFh	FFh	S	
	1						
	2						
	3						
	4						
	5						
	6						
3009h	7						
	0		MSB		00h		
	1						
	2	—	Fixed to "0h"	0h			—
	3	—	Fixed to "0h"	0h			—
	4	—	Fixed to "0h"	0h			—
	5	—	Fixed to "0h"	0h			—
6	—	Fixed to "0h"	0h			—	
300Ah	7						
	0	CPWAIT_TIME [9:0]	LSB	0h	B6h	S	
	1						
	2						
	3						
	4						
	5						
6							
300Bh	7						
	0		MSB		A0h		
	1						
	2	—	Fixed to "0h"	0h			—
	3	—	Fixed to "0h"	0h			—
	4	—	Fixed to "0h"	0h			—
	5	—	Fixed to "1h"	1h			—
6	—	Fixed to "0h"	0h			—	
301Ch	7						
	0	WINMODE [3:0]	Window mode setting 0: All-pixel mode 1: Horizontal/Vertical 2/2-line binning 4: Window cropping mode	0h	00h	V	
	1						
	2						
	3						
	4						
	5						
6							
	7	—	Fixed to "0h"	0h		—	
		—	Fixed to "0h"	0h		—	
		—	Fixed to "0h"	0h		—	
		—	Fixed to "0h"	0h		—	

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3020h	0	HADD	Mode setting 0h: All-pixel mode 1h: Horizontal 2 binning	0h	00h	V
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3021h	0	VADD	Mode setting 0h: All-pixel mode 1h: Vertical 2 binning	0h	00h	V
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3022h	0	ADDMODE [1:0]	Mode setting 0h: All-pixel mode 1h: Horizontal/Vertical 2/2-line binning	0h	00h	V
	1					
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—

Address	bit	Register name	Description	Default value after reset		Reflection timing	
				By register	By address		
3024h	0	VMAX [19:0]	LSB	008CAh	CAh	V	
	1		When sensor master mode vertical span setting.				
	2						
	3						
	4						
	5						
	6						
7							
3025h	0		For details, see the item of "Slave Mode and Master Mode" in the section of "Description of Various Functions".		008CAh		08h
	1						
	2						
	3						
	4						
	5						
	6						
3026h	0	MSB	0h	00h	—		
	1						
	2						
	3						
	4						
	5						
	6						
7							
3028h	0	HMAX [15:0]	LSB	0226h	26h	V	
	1		When sensor master mode horizontal span setting.				
	2						
	3						
	4						
	5						
	6						
7							
3029h	0		For details, see the item of "Slave Mode and Master Mode" in the section of "Description of Various Functions".		0226h		02h
	1						
	2						
	3						
	4						
	5						
	6						
7	MSB						

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3030h	0	HREVERSE	Horizontal direction Readout inversion control 0: Normal 1: Inverted	0h	00h	V
	1	VREVERSE	Vertical direction Readout inversion control 0: Normal 1: Inverted	0h		V
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3031h	0	ADBIT [1:0]	AD conversion bits setting 0: AD 10 bit 1: AD 12 bit (11 bit + digital dither)	1h	01h	V
	1					—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3032h	0	MDBIT	Number of output bit setting 0: 10 bit 1: 12 bit	1h	01h	V
	1	—	Fixed to "0h"	0h		—
	2	—	Fixed to "0h"	0h		—
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
3033h	0	SYS_MODE [3:0]	Output IF mode setting 0: 2376 Mbps (TBD) 2: 2079 Mbps 4: 1782 Mbps 5: 891 Mbps 7: 594 Mbps 8: 1140 / 1485 Mbps 9: 720 Mbps * 2376 Mbps is under planning and it may not be supported.	4h	04h	S
	1					
	2					
	3	—	Fixed to "0h"	0h		—
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3040h	0	PIX_HST [12:0]	LSB	0000h	00h	V
	1		In window cropping mode Start position (Horizontal direction)			
	2					
	3					
	4					
	5					
	6					
3041h	7	Multiples of 2	MSB	0h	00h	—
	0	Fixed to "0h"				
	1					
	2					
	3					
	4					
	5					
3042h	6	PIX_HWIDTH [12:0]	LSB	0F18h	18h	V
	1		In window cropping mode Cropping width (Horizontal direction)			
	2					
	3					
	4					
	5					
	6					
3043h	7	Multiples of 24	MSB	0h	0Fh	—
	0	Fixed to "0h"				
	1					
	2					
	3					
	4					
	5					
3044h	6	PIX_VST [12:0]	LSB	0000h	00h	V
	1		In window cropping mode Start position (Vertical direction)			
	2					
	3					
	4					
	5					
	6					
3045h	7	Designated in Line x2, Multiples of 4	MSB	0h	00h	—
	0	Fixed to "0h"				
	1					
	2					
	3					
	4					
	5					
3045h	6	Fixed to "0h"	0h	0h	—	
	7	Fixed to "0h"	0h			
		Fixed to "0h"	0h			

Address	bit	Register name	Description	Default value after reset		Reflection timing		
				By register	By address			
3046h	0	PIX_VWIDTH [12:0]	LSB	1120h	20h	V		
	1		In window cropping mode Start position (Vertical direction) Designated in Line x 2, Multiples of 4					
	2							
	3							
	4							
	5							
	6							
3047h	7	MSB	0h	11h	—			
	0	Fixed to "0h"						
	1	Fixed to "0h"						
	2	Fixed to "0h"						
	3	Fixed to "0h"						
	4	Fixed to "0h"						
	5	Fixed to "0h"						
3050h	6	Fixed to "0h"	00066h	66h	V			
	7	Fixed to "0h"						
	0	SHR0 [19:0]				Storage time adjustment Designated in line units.		
	1							
	2							
	3							
	4							
5								
3051h	6		SHR0 [19:0]	Storage time adjustment Designated in line units.	00h		V	
	7							
	0	MSB				00h		—
	1							
	2							
	3							
	4							
5								
3052h	6		Fixed to "0h"	0h	00h		—	
	7	Fixed to "0h"						
	0	Fixed to "0h"						
	1	Fixed to "0h"						
	2	Fixed to "0h"						
	3	Fixed to "0h"						
	4	Fixed to "0h"						

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3090h	0	GAIN_PCG_0 [8:0]	LSB	000h	00h	V
	1					
	2					
	3					
	4					
	5					
	6					
	7					
3091h	0		MSB	0h	00h	—
	1	—	Fixed to "0h"			
	2	—	Fixed to "0h"			
	3	—	Fixed to "0h"			
	4	—	Fixed to "0h"			
	5	—	Fixed to "0h"			
	6	—	Fixed to "0h"			
	7	—	Fixed to "0h"			
30C0h	0	XVSOUTSEL [1:0]	XVS pin setting in master mode 0: Fixed to Low 2: VSYNC output	2h	2Ah	I
	1					
	2	XHSOUTSEL [1:0]	XHS pin setting in master mode 0: Fixed to Low 2: HSYNC output	2h		I
			3			
	4	—	Fixed to "2h"	2h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—
30C1h	0	XVS_DRV [1:0]	XVS pin setting 0: XVS output (Master mode) 3: HiZ (Slave mode)	3h	0Fh	S
	1					
	2	XHS_DRV [1:0]	XHS pin setting 0: XHS output (Master mode) 3: HiZ (Slave mode)	3h		S
			3			
	4	—	Fixed to "0h"	0h		—
	5	—	Fixed to "0h"	0h		—
	6	—	Fixed to "0h"	0h		—
	7	—	Fixed to "0h"	0h		—

Address	bit	Register name	Description	Default value after reset		Reflection timing	
				By register	By address		
30CCh	0	—	Fixed to "0h"	0h	00h	—	
	1	—	Fixed to "0h"	0h		—	
	2	—	Fixed to "0h"	0h		—	
	3	—	Fixed to "0h"	0h		—	
	4	XVSLNG [1:0]	XVS pulse width setting in master mode. 0: 1H 1: 2H 2: 4H 3: 8H	0h		00h	I
	5						
	6	—	Fixed to "0h"	0h		—	
7	—	Fixed to "0h"	0h	—			
30CDh	0	—	Fixed to "0h"	0h	00h	—	
	1	—	Fixed to "0h"	0h		—	
	2	—	Fixed to "0h"	0h		—	
	3	—	Fixed to "0h"	0h		—	
	4	XHSLNG [1:0]	XHS pulse width setting in master mode. 0: 16clock 1: 32clock 2: 64clock 3: 128clock	0h		00h	I
	5						
	6	—	Fixed to "0h"	0h		—	
7	—	Fixed to "0h"	0h	—			
30E2h	0	BLKLEVEL [9:0]	LSB Black level offset value setting 10-bit readout mode: 1digit/1h 12-bit readout mode: 4digit/1h	032h	32h	V	
	1						
	2						
	3						
	4						
	5						
	6						
7							
30E3h	0	—	MSB Fixed to "0h"	0h	00h	—	
	1						
	2						
	3						
	4						
	5						
	6						
7							

(2) Registers corresponding to address = 31**h.

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3115h	[7:0]	INCKSEL1 [7:0]	The value is set according to INCK. Refer to "INCK setting"	00h	00h	S
3116h	[7:0]	INCKSEL2 [7:0]	The value is set according to INCK. Refer to "INCK setting"	28h	28h	S
3118h	0	INCKSEL3 [10:0]	LSB	0C0h	C0h	S
	1					
	2					
	3					
	4					
	5					
	6					
	7					
3119h	0	—	MSB	0h	00h	—
	1					
	2					
	3					
	4					
	5					
	6					
	7					
311Ah	0	INCKSEL4 [10:0]	LSB	0E0h	0E0h	S
	1					
	2					
	3					
	4					
	5					
	6					
	7					
311Bh	0	—	MSB	0h	00h	—
	1					
	2					
	3					
	4					
	5					
	6					
	7					
311Eh	[7:0]	INCKSEL5 [7:0]	The value is set according to INCK. Refer to "INCK setting"	28h	28h	S

(3) Registers corresponding to address = 35**h.

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
35A0h	[7:0]	—	Set to "38h"	00h	00h	S

(4) Registers corresponding to address = 37**h.

Address	bit	Register name	Description	Default value after reset		Reflection timing
				By register	By address	
3701h	[7:0]	ADBIT1 [7:0]	The value is set according to AD Conversion bits 00h: AD 10-bit 03h: AD 12-bit (11 bit + digital dither)	03h	03h	I

(5) Registers corresponding to address = 40**h.

Address	bit	Register name	Description	Default value		Reflection timing	
				By register	By address		
4001h	0	LANEMODE [2:0]	Output interface selection 1: CSI-2 2lane 3: CSI-2 4lane	3h	03h	S	
	1						
	2	—	Fixed to "0h"	0h		—	
	3	—	Fixed to "0h"	0h		—	
	4	—	Fixed to "0h"	0h		—	
	5	—	Fixed to "0h"	0h		—	
	6	—	Fixed to "0h"	0h		—	
4004h	[7:0]	TXCLKESC_FREQ [15:0]	The value is set according to INCK. Refer to "INCK setting"	1290h	90h	S	
4005h	[7:0]				12h		
400Ch	0	INCKSEL6	The value is set according to INCK. Refer to "INCK setting"	1h	01h	S	
	1	—	Fixed to "0h"	0h		—	
	2	—	Fixed to "0h"	0h		—	
	3	—	Fixed to "0h"	0h		—	
	4	—	Fixed to "0h"	0h		—	
	5	—	Fixed to "0h"	0h		—	
	6	—	Fixed to "0h"	0h		—	
7	—	Fixed to "0h"	0h	—			
4018h	[7:0]	TCLKPOST [15:0]	Global timing setting	00B7h	B7h	S	
4019h	[7:0]				00h		
401Ah	[7:0]	TCLKPREPARE [15:0]	Global timing setting	0067h	67h	S	
401Bh	[7:0]				00h		
401Ch	[7:0]	TCLKTRAIL [15:0]	Global timing setting	006Fh	6Fh	S	
401Dh	[7:0]				00h		
401Eh	[7:0]	TCLKZERO [15:0]	Global timing setting	01DFh	DFh	S	
401Fh	[7:0]				01h		
4020h	[7:0]	THSPREPARE [15:0]	Global timing setting	006Fh	6Fh	S	
4021h	[7:0]				00h		
4022h	[7:0]	THSZERO [15:0]	Global timing setting	00CFh	CFh	S	
4023h	[7:0]				00h		
4024h	[7:0]	THSTRAIL [15:0]	Global timing setting	006Fh	6Fh	S	
4025h	[7:0]				00h		
4026h	[7:0]	THSEXIT [15:0]	Global timing setting	00B7h	B7h	S	
4027h	[7:0]				00h		
4028h	[7:0]	TLPX [15:0]	Global timing setting	005Fh	5Fh	S	
4029h	[7:0]				00h		
4074h	0	INCKSEL7 [2:0]	The value is set according to INCK. Refer to "INCK setting"	0h	00h	S	
	1						
	2	—	Fixed to "0h"			0h	—
	3	—	Fixed to "0h"			0h	—
	4	—	Fixed to "0h"			0h	—
	5	—	Fixed to "0h"			0h	—
	6	—	Fixed to "0h"			0h	—
7	—	Fixed to "0h"	0h	—			

Readout Drive mode

Operating mode

The table below lists the operating modes available with this sensor.

Mode	Lane	Data rate [Mbps/Lane]	AD conversion [bit]	Output bit width [bit]	Frame rate [frame/s]	Recording Pixels		INCK [MHz]	1H period [Clock]	
						H [pixels]	V [lines]			
All pixel	2	2079	10	10	30	3840	2160	27, 37.125, 74.25	1100 ^(*1)	
			12	12						
		1782	10	10	30			27, 37.125, 74.25	1100 ^(*1)	
			12	12						
		1440	10	10	30.01			24, 72	1066 ^(*2)	
		891	10	10	15			27, 37.125, 74.25	2200 ^(*1)	
			12	12						
		720	10	10	15.74			24, 72	2032 ^(*2)	
		594	10	10	10			27, 37.125, 74.25	3300 ^(*1)	
			12	12						
		4	2376 (TBD)	10	10			90	27, 37.125, 74.25	366 ^(*1)
			2079	10	10			60	27, 37.125, 74.25	550 ^(*1)
	12			12						
	1782		10	10	60			27, 37.125, 74.25	550 ^(*1)	
			12	12						
	1485		10	10	60			27, 37.125, 74.25	550 ^(*1)	
	1440		10	10	60.03			24, 72	533 ^(*2)	
			12	12	30.01			24, 72	1066 ^(*2)	
	891		10	10	30			27, 37.125, 74.25	1100 ^(*1)	
			12	12						
	720		10	10	30.01			24, 72	1066 ^(*2)	
			12	12					1280 ^(*2)	
	594	10	10	25	27, 37.125, 74.25			1320 ^(*1)		
		12	12	20				1650 ^(*1)		

(*1) Clock frequency = 74.25 [MHz]

(*2) Clock frequency = 72 [MHz]

(Note) Regarding Data rate = 2376 Mbps/Lane, it is under planning and it may not be supported.

Mode	Lane	Data rate [Mbps/Lane]	AD conversion [bit]	Output bit width [bit]	Frame rate [frame/s]	Recording Pixels		INCK [MHz]	1H period [Clock*]
						H [pixels]	V [lines]		
Horizontal/ Vertical 2/2-line binning	2	2079	10	12	30	1920	1080	27, 37.125, 74.25	1100 (*1)
		1782	10	12	30			27, 37.125, 74.25	1100 (*1)
		891	10	12	15			27, 37.125, 74.25	2200 (*1)
		594	10	12	10			27, 37.125, 74.25	3300 (*1)
	4	2079	10	12	60			27, 37.125, 74.25	550 (*1)
		1782	10	12	60			27, 37.125, 74.25	550 (*1)
		1440	10	12	30.01			24, 72	1066 (*2)
		891	10	12	30			27, 37.125, 74.25	1100 (*1)
		720	10	12	25			24, 72	1280 (*2)
		594	10	12	20			27, 37.125, 74.25	1650 (*1)

(*1) Clock frequency = 74.25 [MHz]

(*2) Clock frequency = 72 [MHz]

Image Data Output Format (CSI-2 output)

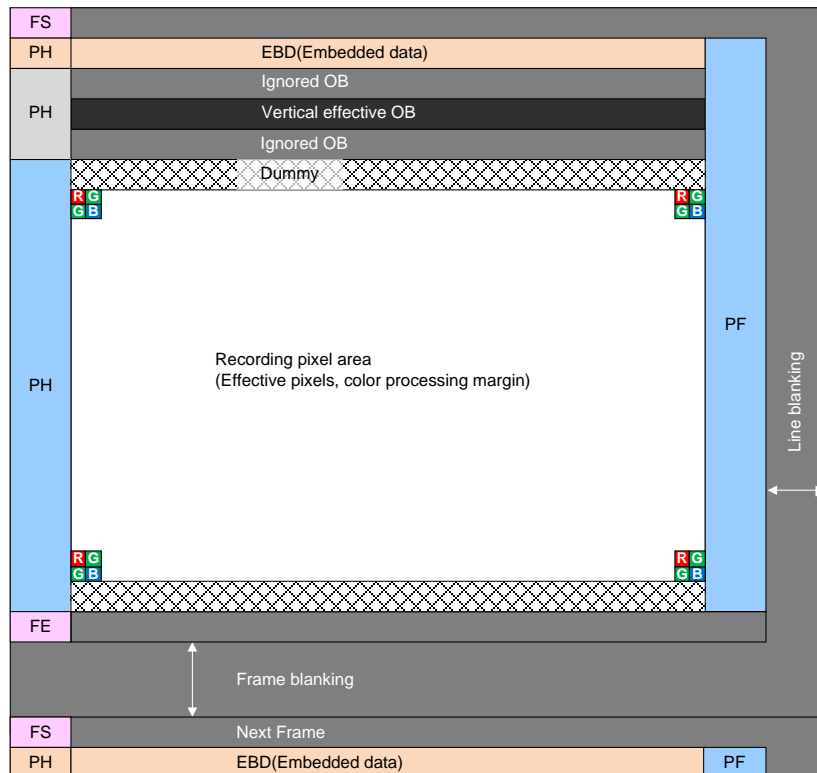
Frame Format

Each line of each image frame is output like the General Frame Format of CSI-2. The settings for each packet header are shown below.

DATA Type

Header [5:0]	Name	Setting register (I ² C)	Description
00h	Frame Start Code	N/A	FS
01h	Frame End Code	N/A	FE
10h	NULL	N/A	Invalid data
12h	Embedded Data	N/A	Embedded data
2Bh	RAW10	Address: 319Dh MDBIT [0]	0A0Ah
2Ch	RAW12		0C0Ch
37h	OB Data	N/A	Vertical OB line data

Frame Structure



Frame Structure of CSI-2 output

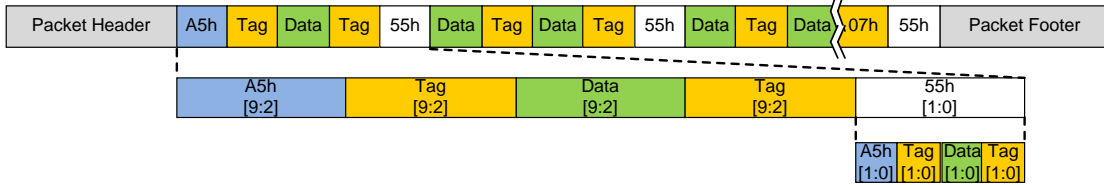
Embedded Data Line

The Embedded data line is output in a line following the sync code FS.

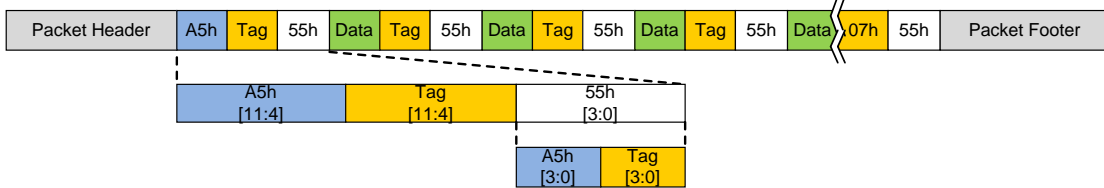
Embedded Data Format



RAW10



RAW12



The end of the address and the register value is determined according to the tags embedded in the data.

Embedded Data Line Tag

Tag	Data Byte Description
00h	Illegal Tag. If found treat as end of Data.
07h	End of Data.
AAh	CCI Register Index MSB [15:8]
A5h	CCI Register Index LSB [7:0]
5Ah	Auto increment the CCI index after the data byte – valid data Data byte contains valid CCI register data.
55h	Auto increment the CCI index after the data byte – null data A CCI register does not exist for the current CCI index. The data byte value is the 07h.
FFh	Illegal Tag. If found treat as end of Data.

Specific output examples are shown below.

Pixel (8bit)	bit	I ² C address [HEX]	Data Byte Description	Description
1	[7:0]	—	—	ignored
2	[3:0]	301C[3:0]	WINMODE	
3	[3:0]	—	—	ignored
	[4]	3030[0]	HREVERSE	
	[6:5]	3022[1:0]	ADDMODE	
	[7]	—	—	ignored
4 to 8	[7:0]	—	—	ignored
9	[4:0]	—	—	ignored
	[5]	3030[1]	VREVERSE	
	[7:6]	—	—	ignored
10	[7:0]	—	—	ignored
11	[5:0]	—	—	ignored
	[7:6]	3031[1:0]	ADBIT	
12	[7:0]	—	—	ignored
13	[2:0]	4001[2:0]	LANEMODE	
	[3]	3032[0]	MDBIT	
	[7:4]	3030[3:0]	SYS_MODE	
18 to 23	[7:0]	—	—	ignored
24	[7:0]	3050[7:0]	SHR0	
25	[7:0]	3051[7:0]		
26	[3:0]	3052[3:0]		
	[7:4]	—	—	ignored
27 to 53	[7:0]	—	—	ignored
54	[7:0]	30E2[7:0]	BLKLEVEL	
55	[1:0]	30E3[1:0]		
	[7:2]	—		—
56 to 216	[7:0]	—	—	ignored

Output data is Data[7:0] = 00h from 217 to 224 pixel.
 Output data is Data[7:0] = 07h from 225 to end pixel.

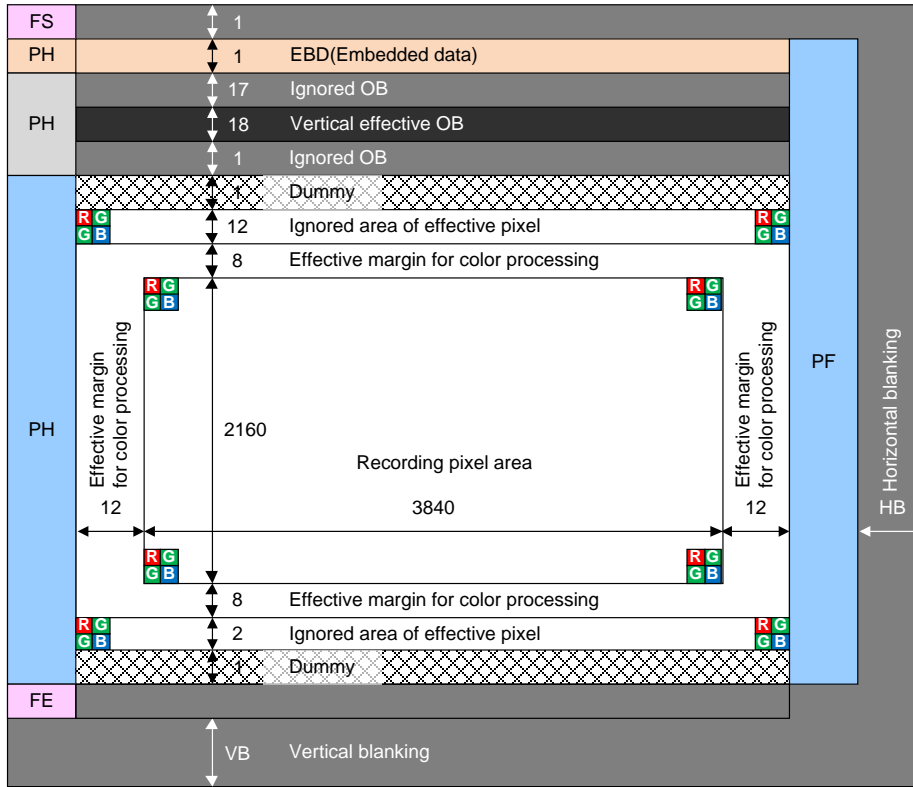
Image Data Output Format

All-pixel mode

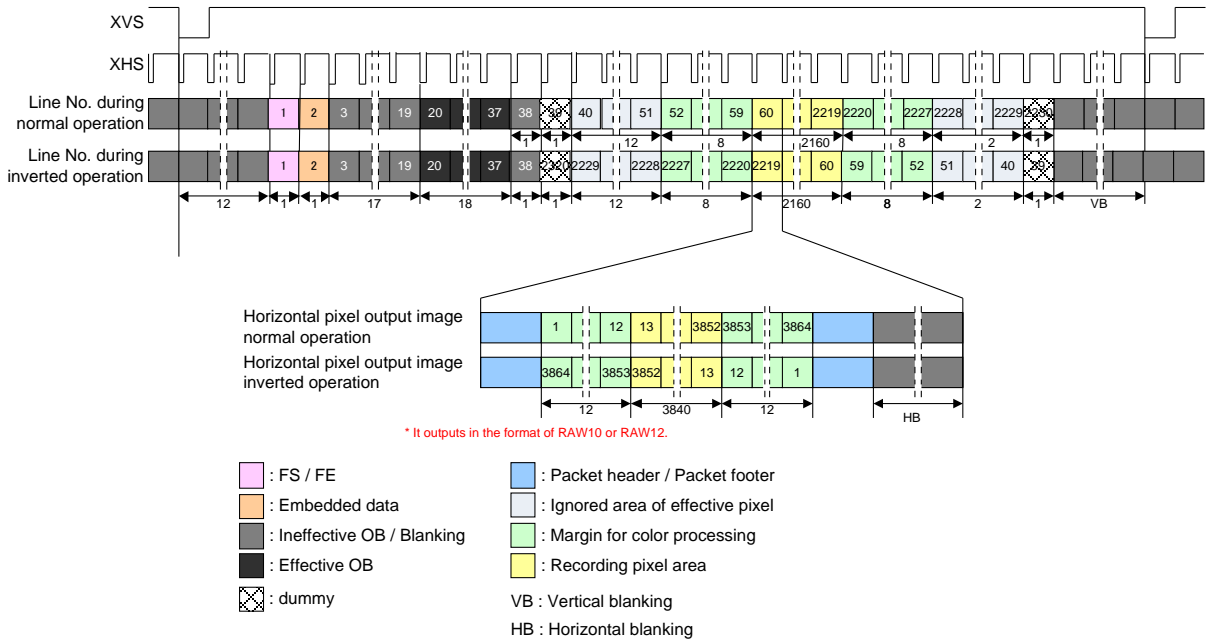
List of Setting Register

Address	bit	Register Name	Initial Value	CSI-2 serial / 2lane						Remarks
				10	15	15.74	30	30	30.01	
				594	891	720	1782	2079	1440	
				44.5	29.7	28.3	14.9	14.9	14.9	
3008h	[7:0]	BCWAIT_TIME	0FFh	Refer to "INCK setting"						
3009h	[1:0]									
300Ah	[7:0]	CPWAIT_TIME	0B6h							
300Bh	[1:0]									
301Ch	[3:0]	WINMODE	0h	0h						All pixel mode
3022h	[1:0]	ADDMODE	0h	0h						All pixel mode
3024h	[7:0]	VMAX	8CAh	8CAh						
3025h	[7:0]									
3026h	[3:0]									
3028h	[7:0]	HMAX	226h	CE4h	898h	7F0h	44Ch	44Ch	42Ah	
3029h	[7:0]									
3030h	[0]	HREVERSE	0h	0h / 1h						0: Nor. , 1: Inv.
	[1]	VREVERSE	0h	0h / 1h						0: Nor. , 1: Inv.
3031h	[1:0]	ADBIT	1h	0h / 1h	0h / 1h	0h	0h / 1h	0h / 1h	0h	0: 10 bit, 1: 12 bit
3032h	[0]	MDBIT	1h	0h / 1h	0h / 1h	0h	0h / 1h	0h / 1h	0h	0: 10 bit, 1: 12 bit
3033h	[3:0]	SYS_MODE	4h	7h	5h	9h	4h	2h	8h	
3115h	[7:0]	INCKSEL1	00h	Refer to "INCK setting"						
3116h	[7:0]	INCKSEL2	28h							
3118h	[7:0]	INCKSEL3	0C0h							
3119h	[2:0]									
311Ah	[7:0]	INCKSEL4	0E0h							
311Bh	[2:0]									
311Eh	[7:0]	INCKSEL5	28h							
3500h to 37FFh	[7:0]	Refer to "Register Map"								
4001h	[2:0]	LAMEMODE	3h	1h						2lane
4004h	[7:0]	TXCLCKES_F REQ	1290h	Refer to "INCK setting"						
4005h	[7:0]									
400Ch	[0]	INCKSEL6	1h							
4018h	[7:0]	TCLKPOST	00B7h	0067h	007Fh	006Fh	00B7h	00D7h	009Fh	Global timing
4019h	[7:0]									
401Ah	[7:0]	TCLKPREPAR E	0067h	0027h	0037h	002Fh	0067h	007Fh	0057h	Global timing
401Bh	[7:0]									
401Ch	[7:0]	TCLKTRAIL	006Fh	0027h	0037h	002Fh	006Fh	007Fh	0057h	Global timing
401Dh	[7:0]									
401Eh	[7:0]	TCLKZERO	01DFh	00B7h	00F7h	00BFh	01DFh	0237h	0187h	Global timing
401Fh	[7:0]									
4020h	[7:0]	THSPREPARE	006Fh	002Fh	003Fh	002Fh	006Fh	0087h	005Fh	Global timing
4021h	[7:0]									
4022h	[7:0]	THSZERO	00CFh	004Fh	006Fh	0057h	00CFh	00EFh	00A7h	Global timing
4023h	[7:0]									
4024h	[7:0]	THSTRAIL	006Fh	002Fh	003Fh	002Fh	006Fh	0087h	005Fh	Global timing
4025h	[7:0]									
4026h	[7:0]	THSEXIT	00B7h	0047h	005Fh	004Fh	00B7h	00DFh	0097h	Global timing
4027h	[7:0]									
4028h	[7:0]	TLPX	005Fh	0027h	002Fh	0027h	005Fh	006Fh	004Fh	Global timing
4029h	[7:0]									
4074h	[2:0]	INCKSEL7	0h	Refer to "INCK setting"						

Address	bit	Register Name	Initial Value	CSI-2 serial / 4lane								Remarks
				20 / 25	25 / 30.01	30	30.01 / 60.03	60	60	60	60	
				594	720	891	1440	1485	1782	2079	2376	
				22.3 / 17.8	17.8 / 14.9	14.9	14.9 / 7.5	7.5	7.5	7.5	7.5	
3008h	[7:0]	BCWAIT_TIME	0FFh	Refer to "INCK setting"								[frame/s]
3009h	[1:0]											
300Ah	[7:0]	CPWAIT_TIME	0B6h	Refer to "INCK setting"								[Mbps/lane]
300Bh	[1:0]											
301Ch	[3:0]	WINMODE	0h	0h								All pixel mode
3022h	[1:0]	ADDMODE	0h	0h								All pixel mode
3024h	[7:0]	VMAX	8CAh	8CAh								
3025h	[7:0]											
3026h	[3:0]											
3028h	[7:0]	HMAX	226h	672h / 528h	500h / 42Ah	44Ch	42Ah / 215h	226h	226h	226h	226h	
3029h	[7:0]											
3030h	[0]	HREVERSE	0h	0h / 1h								0: Nor. , 1: Inv.
	[1]	VREVERSE	0h	0h / 1h								0: Nor. , 1: Inv.
3031h	[1:0]	ADBIT	1h	1h / 0h	1h / 0h	0h / 1h	1h / 0h	0h	0h / 1h	0h / 1h	1h	0: 10 bit, 1: 12 bit
3032h	[0]	MDBIT	1h	1h / 0h	1h / 0h	0h / 1h	1h / 0h	0h	0h / 1h	0h / 1h	1h	0: 10 bit, 1: 12 bit
3033h	[3:0]	SYS_MODE	4h	7h	9h	5h	8h	8h	4h	2h	0h	
3115h	[7:0]	INCKSEL1	00h	Refer to "INCK setting"								
3116h	[7:0]	INCKSEL2	28h									
3118h	[7:0]	INCKSEL3	0C0h									
3119h	[2:0]											
311Ah	[7:0]	INCKSEL4	0E0h									
311Bh	[2:0]											
311Eh	[7:0]	INCKSEL5	28h									
3500h to 37FFh	[7:0]	Refer to "Register Map"										
4001h	[2:0]	LANEMODE	3h	3h								4lane
4004h	[7:0]	TXCLKES_F	1290h	Refer to "INCK setting"								
4005h	[7:0]	REQ										
400Ch	[0]	INCKSEL6	1h									
4018h	[7:0]	TCLKPOST	00B7h	0067h	006Fh	007Fh	009Fh	0007h	00B7h	00D7h	009Fh	Global timing
4019h	[7:0]											
401Ah	[7:0]	TCLKPREPARE	0067h	0027h	002Fh	0037h	0057h	0057h	0067h	007Fh	0057h	Global timing
401Bh	[7:0]											
401Ch	[7:0]	TCLKTRAIL	006Fh	0027h	002Fh	0037h	0057h	00h5F	006Fh	007Fh	0057h	Global timing
401Dh	[7:0]											
401Eh	[7:0]	TCLKZERO	01DFh	00B7h	00BFh	00F7h	0187h	0197h	01DFh	0237h	0187h	Global timing
401Fh	[7:0]											
4020h	[7:0]	THSPREPARE	006Fh	002Fh	002Fh	003Fh	005Fh	005Fh	006Fh	0087h	005Fh	Global timing
4021h	[7:0]											
4022h	[7:0]	THSZERO	00CFh	004Fh	0057h	006Fh	00A7h	00AFh	00CFh	00EFh	00A7h	Global timing
4023h	[7:0]											
4024h	[7:0]	THSTRAIL	006Fh	002Fh	002Fh	003Fh	005Fh	005Fh	006Fh	0087h	005Fh	Global timing
4025h	[7:0]											
4026h	[7:0]	THSEXIT	00B7h	0047h	004Fh	005Fh	0097h	009Fh	00B7h	00DFh	0097h	Global timing
4027h	[7:0]											
4028h	[7:0]	TLPX	005Fh	0027h	0027h	002Fh	004Fh	004Fh	005Fh	006Fh	004Fh	Global timing
4029h	[7:0]											
4074h	[2:0]	INCKSEL7	0h	Refer to "INCK setting"								



Pixel Array Image Drawing in All pixel mode



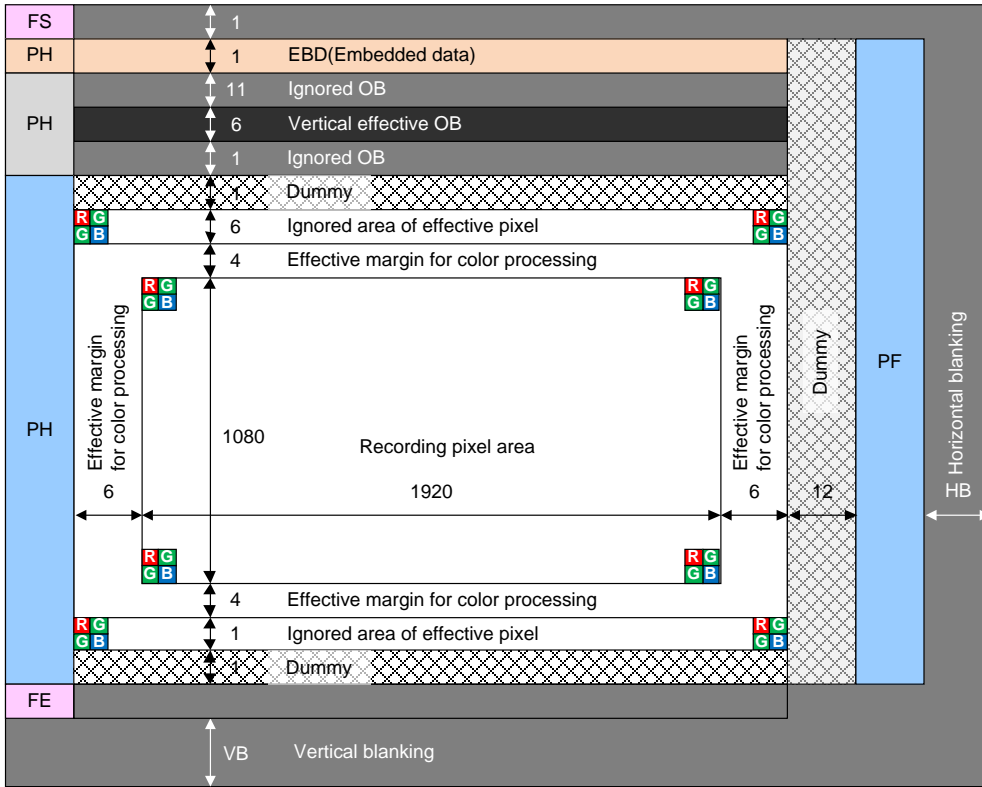
Drive Timing Chart for All pixel mode

Horizontal/Vertical 2/2-line binning mode

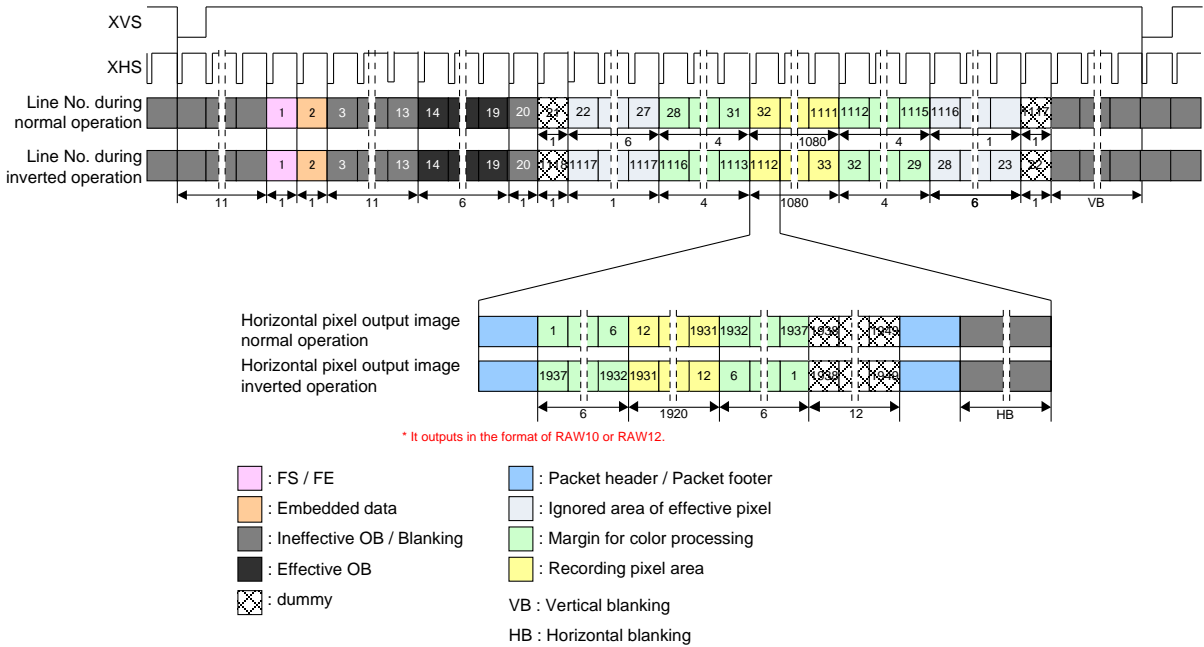
List of Setting Register

Address	bit	Register Name	Initial Value	CSI-2 serial / 2lane				Remarks
				10	15	30	30	
				594	891	1782	2079	
				44.5	29.7	14.9	14.9	
3008h	[7:0]	BCWAIT_TIME	0FFh	Refer to "INCK setting"				
3009h	[1:0]							
300Ah	[7:0]	CPWAIT_TIME	0B6h					
300Bh	[1:0]							
301Ch	[3:0]	WINMODE	0h	0h				All pixel mode
3020h	[0]	HADD	0h	1h				Horizontal 2 binning
3021h	[0]	VADD	0h	1h				Vertical 2 binning
3022h	[1:0]	ADDMODE	0h	1h				H/V 2/2-line binning
3024h	[7:0]	VMAX	8CAh	8CAh				
3025h	[7:0]							
3026h	[3:0]							
3028h	[7:0]	HMAX	226h	CE4h	898h	44Ch	44Ch	
3029h	[7:0]							
3030h	[0]	HREVERSE	0h	0h / 1h				0: Nor. , 1: Inv.
	[1]	VREVERSE	0h	0h / 1h				0: Nor. , 1: Inv.
3031h	[1:0]	ADBIT	1h	0h				10 bit
3032h	[0]	MDBIT	1h	1h				12 bit
3033h	[3:0]	SYS_MODE	4h	7h	5h	4h	2h	
3115h	[7:0]	INCKSEL1	00h	Refer to "INCK setting"				
3116h	[7:0]	INCKSEL2	28h					
3118h	[7:0]	INCKSEL3	0C0h					
3119h	[2:0]							
311Ah	[7:0]	INCKSEL4	0E0h					
311Bh	[2:0]							
311Eh	[7:0]	INCKSEL5	28h					
3500h to 37FFh	[7:0]	Refer to "Register Map"						
4001h	[2:0]	LAMEMODE	3h	1h				2lane
4004h	[7:0]	TXCLCKES_F	1290h	Refer to "INCK setting"				
4005h	[7:0]	REQ						
400Ch	[0]	INCKSEL6						
4018h	[7:0]	TCLKPOST	00B7h	0067h	007Fh	00B7h	00D7h	Global timing
4019h	[7:0]							
401Ah	[7:0]	TCLKPREPARE	0067h	0027h	0037h	0067h	007Fh	Global timing
401Bh	[7:0]							
401Ch	[7:0]	TCLKTRAIL	006Fh	0027h	0037h	006Fh	007Fh	Global timing
401Dh	[7:0]							
401Eh	[7:0]	TCLKZERO	01DFh	00B7h	00F7h	01DFh	0237h	Global timing
401Fh	[7:0]							
4020h	[7:0]	THSPREPARE	006Fh	002Fh	003Fh	006Fh	0087h	Global timing
4021h	[7:0]							
4022h	[7:0]	THSZERO	00CFh	004Fh	006Fh	00CFh	00EFh	Global timing
4023h	[7:0]							
4024h	[7:0]	THSTRAIL	006Fh	002Fh	003Fh	006Fh	0087h	Global timing
4025h	[7:0]							
4026h	[7:0]	THSEXIT	00B7h	0047h	005Fh	00B7h	00DFh	Global timing
4027h	[7:0]							
4028h	[7:0]	TLPX	005Fh	0027h	002Fh	005Fh	006Fh	Global timing
4029h	[7:0]							
4074h	[2:0]	INCKSEL7	0h	Refer to "INCK setting"				

Address	bit	Register Name	Initial Value	CSI-2 serial / 4lane						Remarks	
				20	25	30	30.01	60	60		[frame/s]
				594	720	891	1440	1782	2079		[Mbps/lane]
				22.3	17.8	14.9	14.9	7.5	7.5		1H period [μs]
3008h	[7:0]	BCWAIT_TIME	0FFh	Refer to "INCK setting"							
3009h	[1:0]										
300Ah	[7:0]	CPWAIT_TIME	0B6h	Refer to "INCK setting"							
300Bh	[1:0]										
301Ch	[3:0]	WINMODE	0h	0h						All pixel mode	
3020h	[0]	HADD	0h	1h						Horizontal 2 binning	
3021h	[0]	VADD	0h	1h						Vertical 2 binning	
3022h	[1:0]	ADDMODE	0h	1h						H/V 2/2-line binning	
3024h	[7:0]	VMAX	8CAh	8CAh							
3025h	[7:0]										
3026h	[3:0]										
3028h	[7:0]	HMAX	226h	672h	4FFh	44Ch	42Ah	226h	226h		
3029h	[7:0]										
3030h	[0]	HREVERSE	0h	0h / 1h						0: Nor. , 1: Inv.	
	[1]	VREVERSE	0h	0h / 1h						0: Nor. , 1: Inv.	
3031h	[1:0]	ADBIT	1h	0h						10 bit	
3032h	[0]	MDBIT	1h	1h						12 bit	
3033h	[3:0]	SYS_MODE	4h	7h	9h	5h	8h	4h	2h		
3115h	[7:0]	INCKSEL1	00h	Refer to "INCK setting"							
3116h	[7:0]	INCKSEL2	28h								
3118h	[7:0]	INCKSEL3	0C0h								
3119h	[2:0]										
311Ah	[7:0]	INCKSEL4	0E0h								
311Bh	[2:0]										
311Eh	[7:0]	INCKSEL5	28h								
3500h to 37FFh	[7:0]	Refer to "Register Map"									
4001h	[2:0]	LANEMODE	3h	3h						4lane	
4004h	[7:0]	TXCLCKES_F REQ	1290h	Refer to "INCK setting"							
4005h	[7:0]										
400Ch	[0]	INCKSEL6	1h								
4018h	[7:0]	TCLKPOST	00B7h	0067h	006Fh	007Fh	009Fh	00B7h	00D7h	Global timing	
4019h	[7:0]										
401Ah	[7:0]	TCLKPREPAR E	0067h	0027h	002Fh	0037h	0057h	0067h	007Fh	Global timing	
401Bh	[7:0]										
401Ch	[7:0]	TCLKTRAIL	006Fh	0027h	002Fh	0037h	0057h	006Fh	007Fh	Global timing	
401Dh	[7:0]										
401Eh	[7:0]	TCLKZERO	01DFh	00B7h	00BFh	00F7h	0187h	01DFh	0237h	Global timing	
401Fh	[7:0]										
4020h	[7:0]	THSPREPARE	006Fh	002Fh	002Fh	003Fh	005Fh	006Fh	0087h	Global timing	
4021h	[7:0]										
4022h	[7:0]	THSZERO	00CFh	004Fh	0057h	006Fh	00A7h	00CFh	00EFh	Global timing	
4023h	[7:0]										
4024h	[7:0]	THSTRAIL	006Fh	002Fh	002Fh	003Fh	005Fh	006Fh	0087h	Global timing	
4025h	[7:0]										
4026h	[7:0]	THSEXIT	00B7h	0047h	004Fh	005Fh	0097h	00B7h	00DFh	Global timing	
4027h	[7:0]										
4028h	[7:0]	TLPX	005Fh	0027h	0027h	002Fh	004Fh	005Fh	006Fh	Global timing	
4029h	[7:0]										
4074h	[2:0]	INCKSEL7	0h	Refer to "INCK setting"							



Pixel Array Image Drawing in Horizontal /Vertical 2/2-line binnign mode



Drive Timing Chart for Horizontal /Vertical 2/2-line binnign mode

Window Cropping Mode

Sensor signals are cut out and read out in arbitrary positions.

This function support All-pixel mode, Horizontal/Vertical 2/2-line binning mode, Multiple exposure HDR, Digital overlap HDR and Vertical / Horizontal direction-normal / inverted readout mode of each modes.

Cropping position is set, regarding effective pixel with dumm start position as origin (0, 0) in normal mode direction. That is a start point which is an offset from the origin and cropping width.

Cropping is available from all-pixel scan mode and horizontal period is fixed to the value for this mode. Pixels cropped by horizontal cropping setting are output with left shifted and that extends the horizontal blanking period. Window position and size is used fixed value. (An ignore frame is ouput when it is changed.)

Window cropping image is shown in the figure below.

The same physical pixel area as all-pixel mode is cropped when start position and width are same setting in Horizontal/Vertical 2/2-line binning mode, Multiple exposure HDR, Digital overlap HDR and Vertical / Horizontal direction-normal / inverted readout mode.

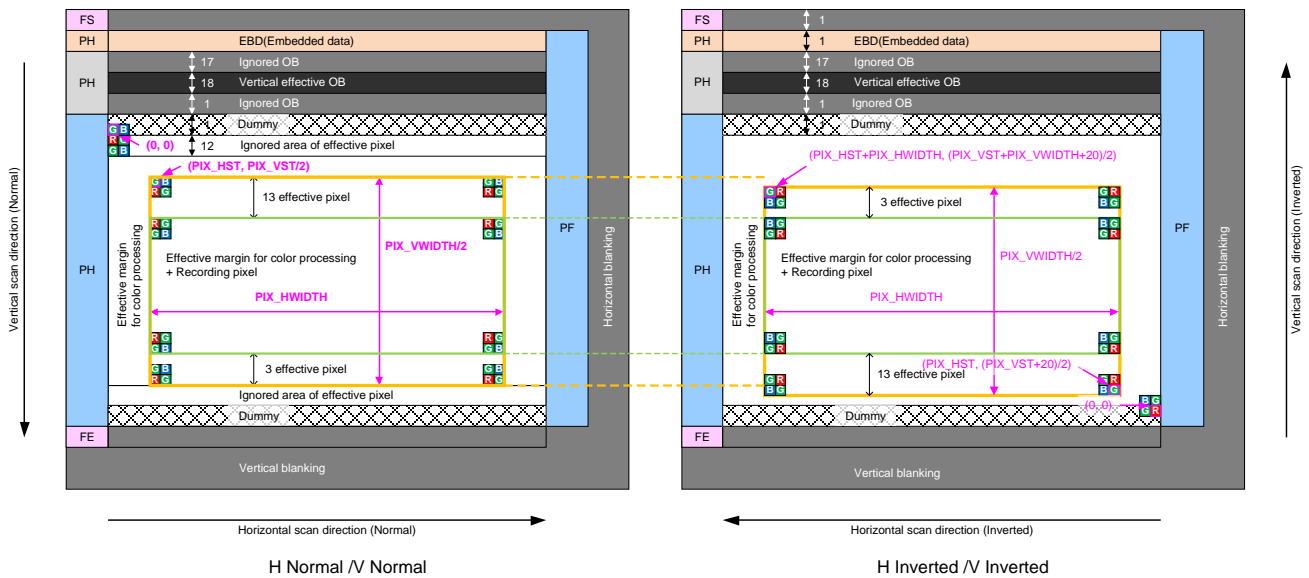


Image Drawing of Window Cropping Mode in Horizontal/Vertical, normal/inverted direction

List of Setting Register

Register	Register details		Initial value	Setting value	Remarks
	Address	bit			
WINMODE	301Ch	[3:0]	0h	4h: Window Cropping mode	
PIX_HST	3040h	[7:0]	0h	Effective pixel Start position (Horizontal direction)	Specified as a multiple of 2
	3041h	[4:0]			
PIX_HWIDTH	3042h	[7:0]	0F18h	Effective pixel Cropping width (Horizontal direction)	Specified as a multiple of 24
	3043h	[4:0]			
PIX_VST	3044h	[7:0]	0h	Effective pixel Star position (Vertical direction) Designated in V units (Linex2)	Specified as a multiple of 4
	3045h	[4:0]			
PIX_VWIDTH	3046h	[7:0]	1120h	Effective pixel Cropping width (Vertical direction) Designated in V units (Linex2)	Specified as a multiple of 4
	3074h	[4:0]			

Restrictions on Window cropping mode

The register settings should satisfy following conditions:

Set WINMODE: 4h.

◆ PIX_VST, PIX_VWIDTH

Set PIX_VST, PIX_VWIDTH to a multiple of 4.

$$\text{PIX_VST} = n_1 \times 4$$

$$\text{PIX_VWIDTH} = n_2 \times 4$$

Cropped start position and width is set multiple of 2 addresses, because PIX_VST, PIX_VWIDTH is internal V address unit.

Cropped area is needed to set pre 13 pixel, rear 3 pixel for signal processing.

◆ PIX_HST, PIX_HWIDTH

Set PIX_HST to a multiple of 2.

Set PIX_HWIDTH to a multiple of 24.

$$\text{PIX_HST} = n_3 \times 2$$

$$\text{PIX_VWIDTH} = n_4 \times 24$$

Where n_{1-4} are integer equal or more than 0.

◆ Frame rate on Window cropping mode

$$\text{Frame rate [frame/s]} = 1 / (V_{\text{TTL}} \times (1\text{H period}))$$

1H period (unit: [μs]) : Fix 1H time in a mode before cropping and refer to the value of "1H period" in the table of "Operating Mode".

Where V_{TTL} is 1frame line length or VMAX.

Description of Various Function

Standby Mode

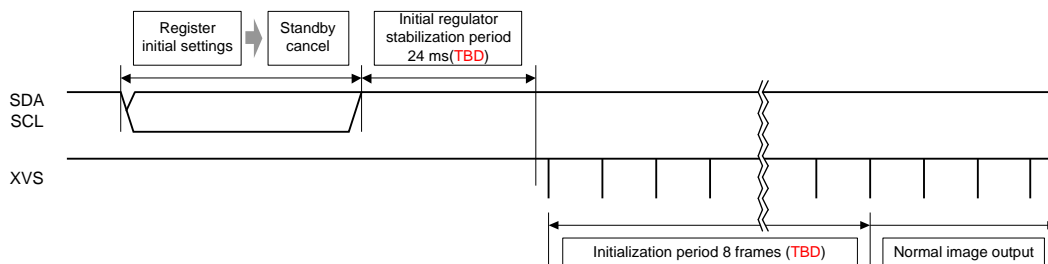
This sensor stops its operation and goes into standby mode which reduces the power consumption by writing “1” to the standby control register STANDBY. Standby mode is also established after power-on or other system reset operation.

List of Standby Mode Setting

Register	Register details		Initial value	Setting value	Remarks
	Address	bit			
STANDBY	3000h	[0]	1h	1h: Standby 0h: Operating	Register communication is executed in standby mode.

The serial communication registers hold the previous values. However, the address registers transmitted in standby mode are overwritten. The serial communication block operates even in standby mode, so standby mode can be canceled by setting the STANDBY register to “0”. Some time is required for sensor internal circuit stabilization after standby mode is canceled. After standby mode is canceled, a normal image is output from the 8 frames(TBD) after internal regulator stabilization 24 ms or more(TBD).

For details of the sequence of setting and cancel standby mode, see the sensor setting flow after power on.



Sequence from Standby Cancel to Stable Image Output

Slave Mode and Master Mode

The sensor can be switched between slave mode and master mode. The switching is made by the XMASTER register. Establish the XMASTER status before canceling the system reset. (Do not switch this register status during operation.)

Input a vertical sync signal to XVS and input a horizontal sync signal to XHS when a sensor is in slave mode. For sync signal interval, input data lines to output for vertical sync signal and 1H period designated in each operating mode for horizontal sync signal. See the section of "Operating mode" for the number of output data line and 1H period.

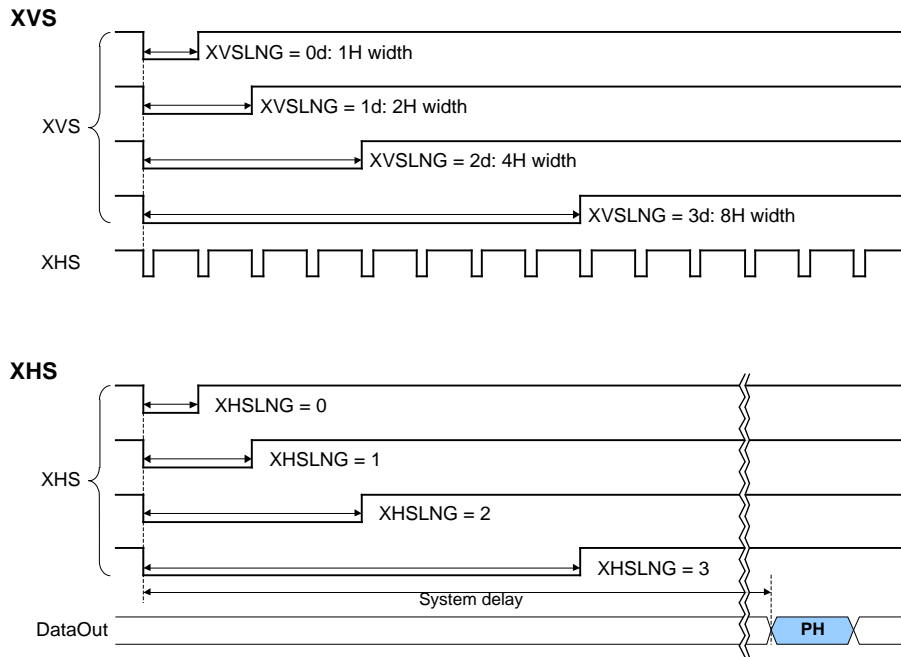
Set the XMSTA register 0h in order to start the operation after setting to master mode. In addition, set the count number of sync signal in vertical direction by the VMAX [19:0] register and the clock number in horizontal direction by the HMAX [15:0] register. See the description of Operation Mode for details of the section of "Operating Modes".

List of Slave and Master Mode Setting

Register	Register details		Initial value	Setting value	Remarks
	Address	bit			
XMASTER	3003h	[0]	0h	0h: Master mode 1h: Slave mode	

List of Register in Master Mode

Register	Register details		Initial value	Setting value	Remarks
	Address	bit			
XMSTA	3002h	[0]	1h	1h: Master operation ready 0h: Master operation start	The master operation starts by setting 0.
VMAX [19:0]	3024h	[7:0]	008CAh	See the item of each drive mode.	Line number per frame designated
	3025h	[7:0]			
	3026h	[3:0]			
HMAX [15:0]	3028h	[7:0]	0226h	See the item of each drive mode.	Clock number per line designated
	3029h	[7:0]			
XVSOUTSEL [1:0]	30C0h	[1:0]	2h	0h: Fixed to Low 2h: VSYNC output	
XHSOUTSEL [1:0]		[3:2]	2h	0h: Fixed to Low 2h: HSYNC output	
XVS_DRV [1:0]	30C1h	[1:0]	3h	0h: XVS output (Master mode) 3h: Hi-z (Slave mode)	
XHS_DRV [1:0]		[3:2]	3h	0h: XHS output (Master mode) 3h: Hi-z (Slave mode)	
XVSLNG [1:0]	30CCh	[5:4]	0h	0h: 1H, 1h: 2H, 2h: 4H, 3h: 8H	XVS low level pulse width designated
XHSLNG [1:0]	30CDh	[6:5]	0h	0h: 16clock, 1h: 32clock 2h: 64clock, 3h: 128clock See the next	XHS low level pulse width designated



XVS/XHS output waveform in sensor master mode

The XVS and XHS are output in timing that set 0 to the register XMSTA. If set 0 to XMSTA during standby, the XVS and XHS are output Kust after standby is released. The XVS and XHS are output asynchronous with other input or output signals. In addition, the output signals are output with a undefined latency time (system delay) relative to the XHS. Therefore, refer to the sync codes output from the sensor and perform synchronization.

Gain Adjustment Function

The Programmable Gain Control (PGC) of this device consists of the analog block and digital block. The total of analog gain and digital gain can be set up to 72dB(TBD) by the GAIN_PCG_0 [8:0] register setting. The same setting is applied in all colors.

The value which is 10/3 times the gain is set to register. (0.3 dB step)

Example)

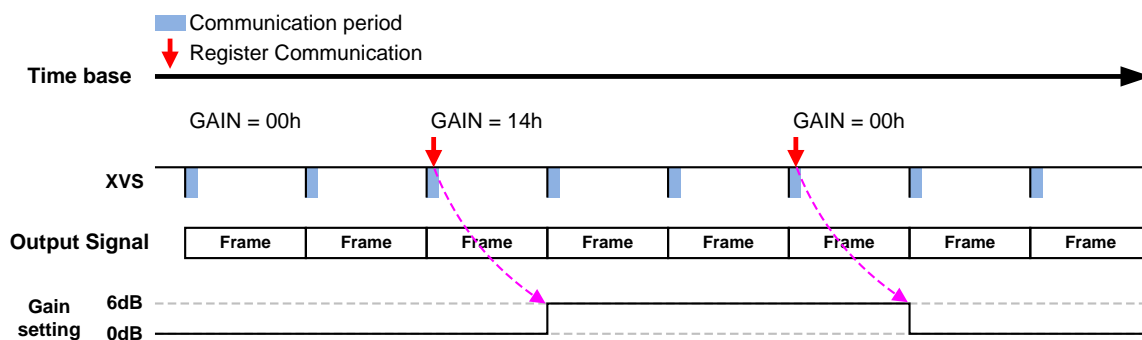
When set to 6 dB: $6 \times 10/3 = 20d$; GAIN = 14h

When set to 12.6 dB: $12.6 \times 10/3 = 42d$; GAIN = 2Ah

List of PGC Register

Register	Register details		Initial value	Setting value	Remarks
	Address	bit		Setting range	
GAIN_PCG_0 [8:0]	3090h	[7:0]	000h	00h-F0h(TBD) (0d-240d)	Setting value: Gain [dB] $\times 10/3$ (0.3 dB step)
	3091h	[1]			

The gain setting is reflected at the next frame that the communication is performed as shown below.



Gain Reflection Timing

Black Level Adjustment Function

The black level offset (offset variable range: 000h to 3FFh) can be added relative to the data in which the digital gain modulation was performed by the BLKLEVEL [9:0] register.

When the BLKLEVEL setting is increased by 1 LSB, the black level is increased by 1 LSB at 10.

Note that the offset unit changes according to the output bit setting.

When the output data length is 10-bit output, increasing the register setting value by 1h increases the black level by 1 LSB. When the output data length is 12-bit output, increasing the register setting value by 1h increases the black level by 4 LSB.

Use with values shown below is recommended.

10-bit output: 032h (50d)

12-bit output: 032h (200d)

List of Black Level Adjustment Register

Register	Register details		Initial value	Setting value
	Address	bit		
BLKLEVEL [9:0]	30E2h	[7:0]	032h	000h to 3FFh
	30E3h	[1:0]		

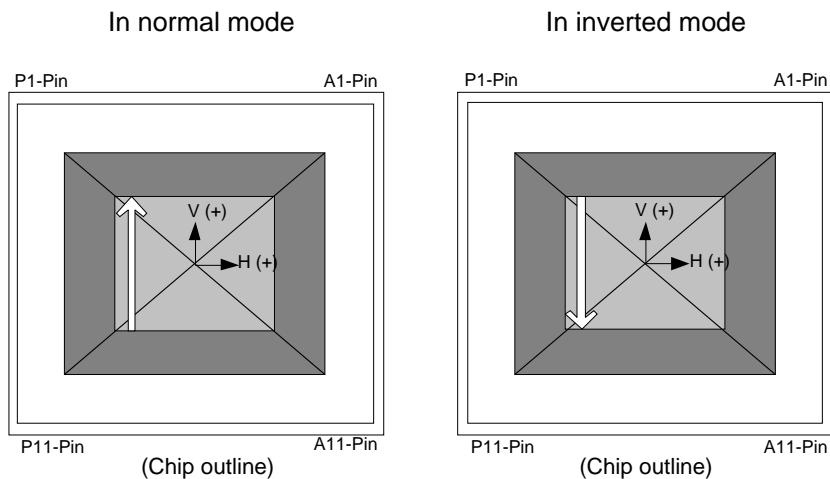
Normal Operation and Inverted Operation

The sensor readout direction (normal / inverted) in vertical direction can be switched by VREVERSE register settings and in horizontal direction can be switched by the HREVERSE register setting. See the section of “Operating Modes” for the order of readout lines in normal and inverted modes. See the section of “List of Setting Register” for the other register settings.

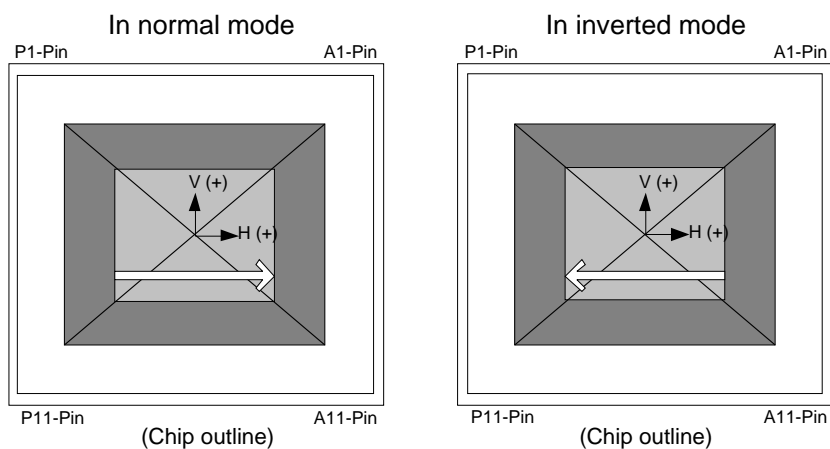
One invalid frame is generated when reading immediately after the readout vertical direction change in order to switch the normal operation and inversion between frames.

List of Drive Direction Setting Register

Register	Register details		Initial value	Setting value
	Address	bit		
HREVERSE	3030h	[0]	0h	0h: Normal 1h: Inverted
VREVERSE		[1]	0h	0h: Normal 1h: Inverted



Normal and Inverted Drive Outline in Vertical Direction (TOP VIEW)



Normal and Inverted Drive Outline in Horizontal Direction (TOP VIEW)

Shutter and Integration Time Settings

This sensor has a variable electronic shutter function that can control the integration time in line units. In addition, this sensor performs rolling shutter operation in which electronic shutter and readout operation are performed sequentially for each line.

Note) For integration time control, an image which reflects the setting is output from the frame after the setting changes.

Example of Integration Time Setting

The sensor's integration time is obtained by the following formula.

$$\text{Integration time} = 1 \text{ frame period} - \text{SHR0} \times (1\text{H period})$$

- *1 The frame period is determined by the input XVS when the sensor is operating in slave mode, or the register VMAX value in master mode. The frame period is designated in 1H units, so the time is determined by (Number of lines × 1H period).
- *2 See "Operating Modes" for the 1H period.

In this section, the shutter operation and storage time are shown as in the figure below with the time sequence on the horizontal axis and the vertical address on the vertical axis. For simplification, shutter and readout operation are noted in line units.

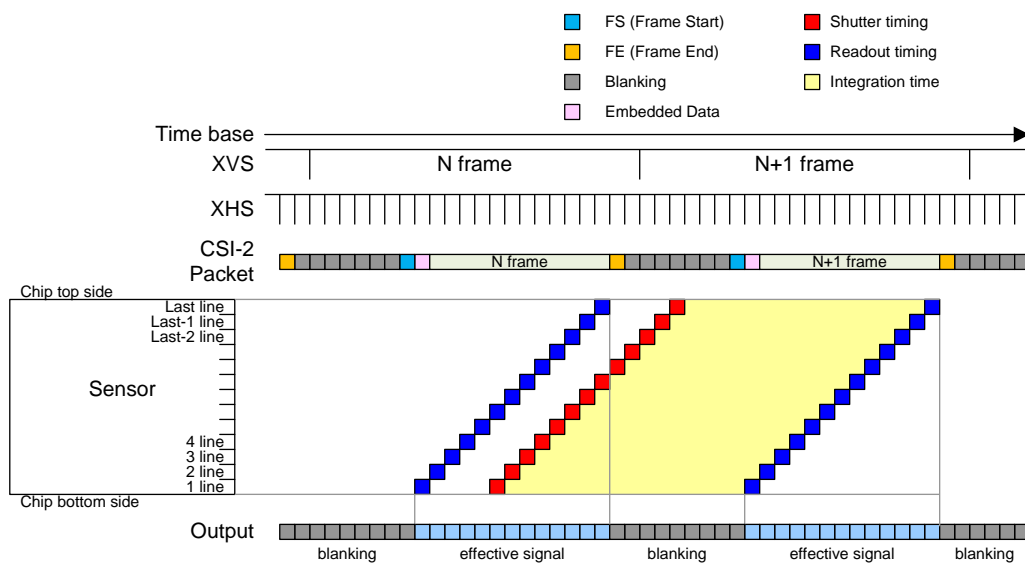


Image Drawing of Shutter Operation

Normal Exposure Operation (Controlling the Integration Time in 1H Units)

The integration time can be controlled by varying the electronic shutter timing. In the electronic shutter settings, the integration time is controlled by the SHR0 [19:0] register. Set SHR0 [19:0] to a value between 8 and (Number of lines per frame - 4). When the sensor is operating in slave mode, the number of lines per frame is determined by the XVS interval (number of lines), using the input XHS interval as the line unit. When the sensor is operating in master mode, the number of lines per frame is determined by the VMAX register. The number of lines per frame differs according to the operating mode.

Registers Used to Set the Integration Time in 1H Units

Register	Register details		Initial value	Setting value
	Address	bit		
SHR0 [19:0]	3050h	[7:0]	00066h	Sets the shutter sweep time. 8 to (Number of lines per frame - 4) * Others: Setting prohibited
	3051h	[7:0]		
	3052h	[3:0]		
VMAX [19:0]	3024h	[7:0]	008CAh	Sets the number of lines per frame (only in master mode). See "Operating Modes" for the setting value in each mode.
	3025h	[7:0]		
	3026h	[3:0]		

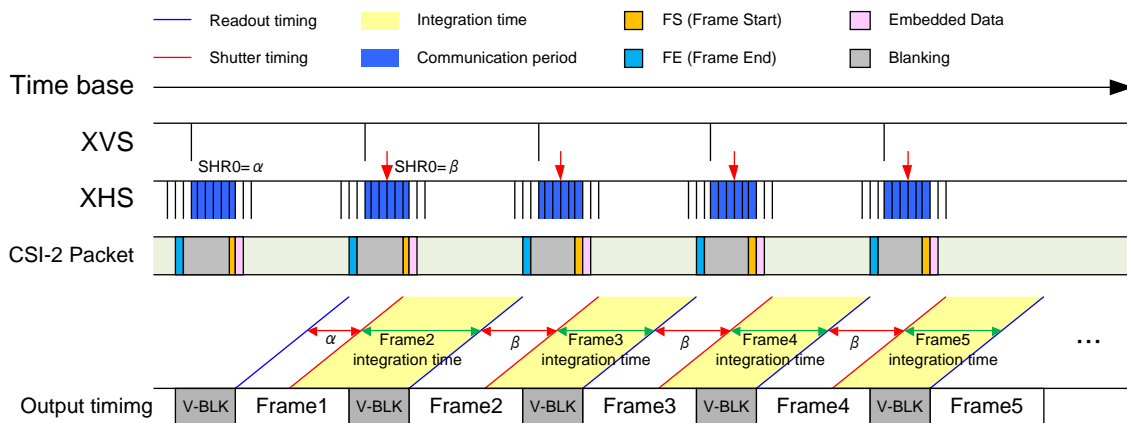


Image Drawing of Integration Time Control within a Frame

Long Exposure Operation (Control by Expanding the Number of Lines per Frame)

Long exposure operation can be performed by lengthening the frame period.

When the sensor is operating in slave mode, this is done by lengthening the input vertical sync signal (XVS) pulse interval.

When the sensor is operating in master mode, it is done by designating a larger register VMAX [19:0] value compared to normal operation. When the integration time is extended by increasing the number of lines, the rear V blanking increases by an equivalent amount.

Although the maximum value of long exposure operation changes in each modes, the maximum of long time exposure is approximately **TBD** s.

When set to a number of V lines or more than that noted for each operating mode, the imaging characteristics are not guaranteed during long exposure operation.

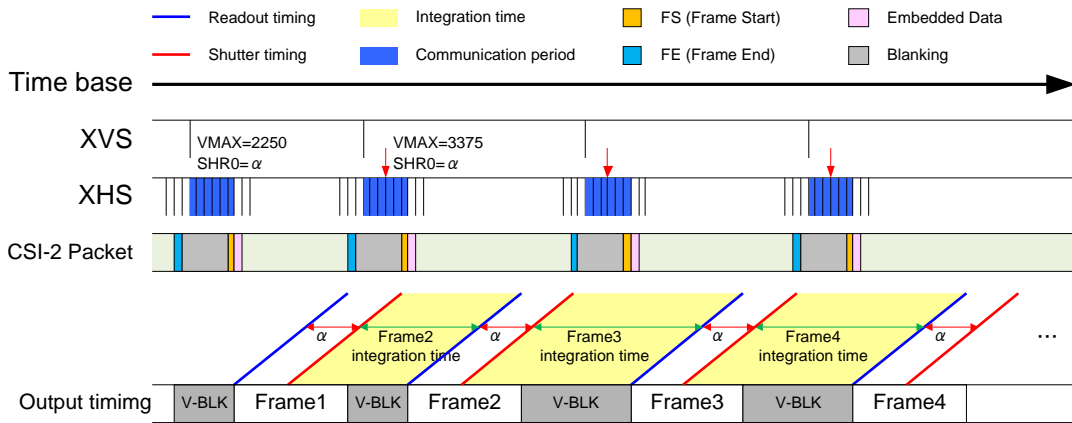


Image Drawing of Long Integration Time Control by Adjusting the Frame Period

Example of Integration Time Settings

The example of register setting for controlling the storage time is shown below.

Example of Integration Time Settings

Operation	Sensor setting (register)		Integration time
	VMAX*	SHR0**	
All-pixel scan mode	2250	2246	4H
		⋮	⋮
		N	(2250 - N) H
		⋮	⋮
		8	2242H

* In sensor master mode. In slave mode, the interval is the same as XVS input.

** The SHR0 setting value (N) is set between "8" and "the VMAX value (M) - 4".

Signal Output
CSI-2 output

The output formats of this sensor support the following modes.

CSI-2 serial 2 Lane / 4 Lane, RAW10 / RAW12

The 2 Lane / 4 Lane serial signal output method using this sensor is described below.

Complied with the CSI-2, data is output using 2 Lane / 4 Lane. The image data is output from the CSI-2 output pin. The DMO1P / DMO1N are called the Lane1 data signal, the DMO2P / DMO2N are called the Lane2 data signal, the DMO3P / DMO3N are called the Lane3 data signal, the DMO4P / DMO4N are called the Lane4 data signal. In addition, the clock signals are output from DCKP / DCKN of the CSI-2 pins.

In 2 Lane mode, data is output from Lane1 and Lane2. In 4 Lane mode, data is output from Lane1, Lane2, Lane3 and Lane4.

The bit rate maximum value are **2376 Mbps / Lane (TBD)** in 4 Lane mode and 2079 Mbps / Lane in 2 Lane mode..

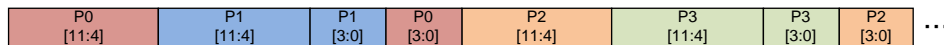
The select of RAW10 / RAW12 is set by the register: MDBIT [0]. The number of output lanes is set by the register: LANEMODE [2:0]. Unused lanes (when setting 2 lanes; DMO3P / DMO3N, DMO4P / DMO4N) output signals conformed to MIPI standard.

Register	Register details		Initial value	Setting value
	Address	bit		
MDBIT	3032h	[0]	1h	0h: RAW10 1h: RAW12
LANEMODE [2:0]	4011h	[2:0]	3h	1h: 2lane 3h: 4lane

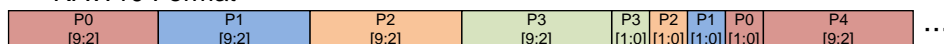
The formats of RAW12 and RAW10 are shown below.



→ RAW12 Format

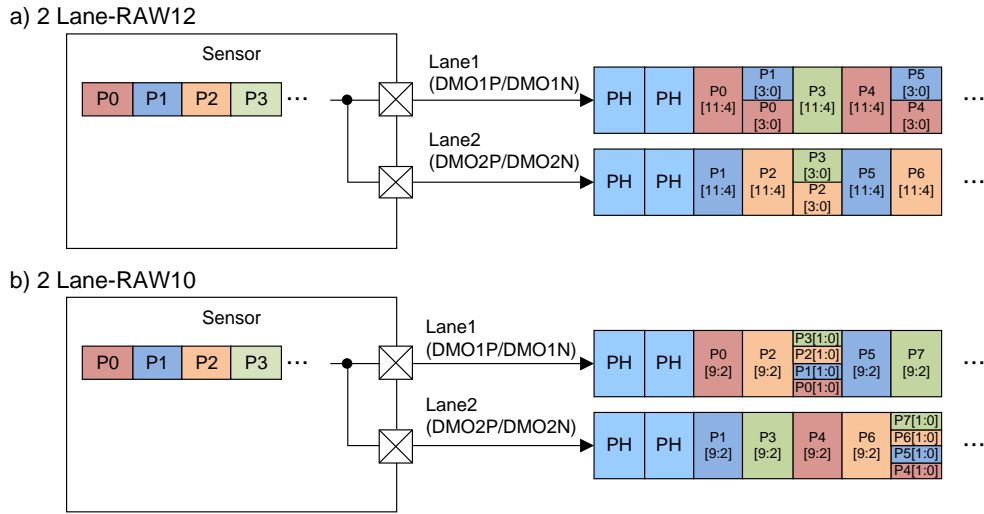


→ RAW10 Format

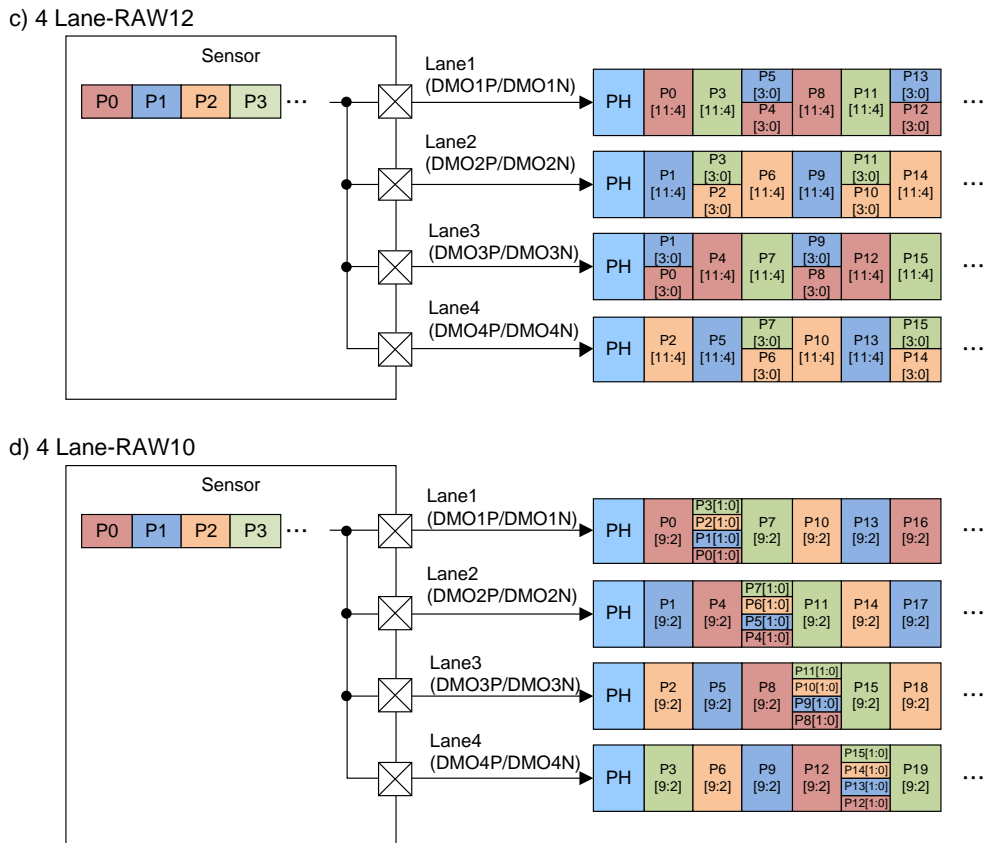


The Example of Format of RAW12 / RAW10

The each format of 2 Lane and 4 Lane are shown below.



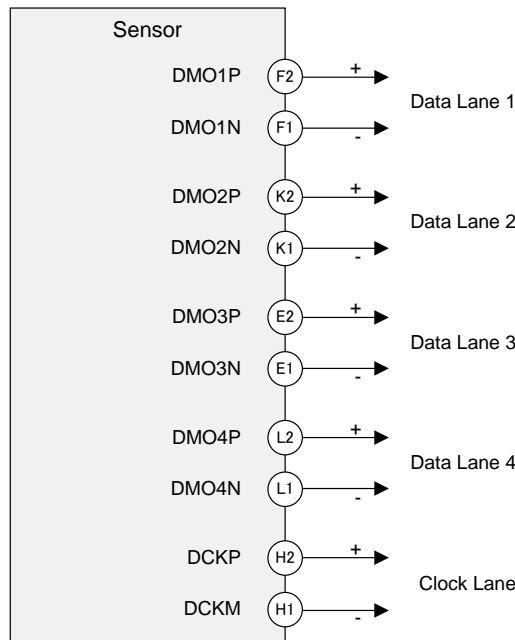
2 Lane Output Format



4 Lane Output Format

MIPI Transmitter

Output pins (DMOP1, DMOM1, DMOP2, DMOM2, DMOP3, DMOM3, DMOP4, DMOM4, DCKP, DCKM) are described in this section.



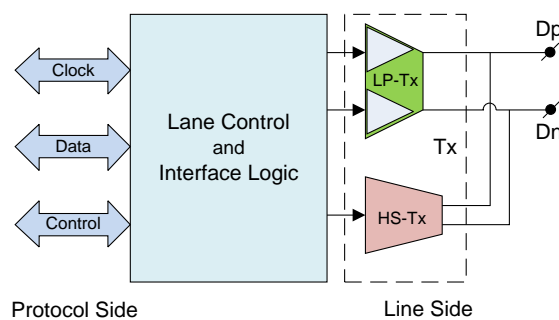
Relationship between Pin Name and MIPI Output Lane

The pixel signals are output by the CSI-2 High-speed serial interface.

See the MIPI Standard

- MIPI Alliance Standard for Camera Serial Interface 2 (CSI-2) Version 1.20.00
- MIPI Alliance Specification for D-PHY Version 1.20.00

The CSI-2 transfers one bit with a pair of differential signals. The transmitter outputs differential current signal after converting pixel signals to it. Insert external resistance in differential pair in a series or use cells with a built-in resistance on the Receiver side. When inserting an external resistor, as close as possible to the Receiver. The differential signals maintain a constant interval and reach the receiver with the shortest wiring length possible to avoid malfunction. The maximum bit rate of each Lane is **2376 Mbps / Lane (TBD)**.



Universal Lane Module Functions

Number of Internal A/D Conversion Bits Setting

The number of internal A/D conversion bits can be selected from 10 bits or 12 bits by the register ADBIT. See the section of "Operating Modes" for the correspondence with each mode.

List of Bit Width Selection

Register	Register details		Initial value	Setting value
	Address	bit		
ADBIT	3031h	[0]	1h	0: 10 bit 1: 12 bit

Output Signal Range

In CSI-2 output mode, the sensor output has either a 10 bit or 12 bit gradation, but output is not performed over the full range, and the maximum output value is the 3FFh value (10 bit output) and the FFFh one (12 bit output). The output range for each output gradation is shown in the table below.

Output Gradation and Output Range (CSI-2 Output)

Output gradation	Output value	
	Min.	Max.
10 bit	000h	3FFh
12 bit	000h	FFFh

INCK Setting

The available operation mode varies according to INCK frequency. Input either 24 MHz, 27 MHz, 37.125 MHz, 72 MHz or 74.25 MHz for INCK frequency. The INCK setting register and the list of INCK setting are shown in the table below.

INCK Setting Register

Data rate: 2376Mbps / lane (TBD)

Register	Register details		Initial value	INCK		
	Address	Bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	00h	00h	00h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	0108h	0100h	0100h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	01h	01h	01h
INCKSEL7	4074h	[2:0]	00h	00h	00h	00h

Data rate: 2079Mbps / lane

Register	Register details		Initial value	INCK		
	Address	bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	02h	02h	02h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00E7h	00E0h	00E0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	01h	01h	01h
INCKSEL7	4074h	[2:0]	00h	00h	00h	00h

Data rate: 1782Mbps / lane

Register	Register details		Initial value	INCK		
	Address	bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	04h	04h	04h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00C6h	00C0h	00C0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	01h	01h	01h
INCKSEL7	4074h	[2:0]	00h	00h	00h	00h

Data rate: 1485 Mbps / lane

Register	Register details		Initial value	INCK		
	Address	bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	08h	08h	08h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00A5h	00A0	00A0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	01h	01h	01h
INCKSEL7	4074h	[2:0]	00h	00h	00h	00h

Data rate: 1440Mbps / lane

Register	Register details		Initial value	INCK	
	Address	bit		24 [MHz]	72 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	54h	F8h
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	3Bh	B0h
SYS_MODE	3034h	[7:0]	04h	08h	08h
INCKSEL1	3115h	[7:0]	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00B4h	00A0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00FCh	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	0600h	1200h
INCKSEL6	400Ch	[0]	01h	01h	01h
INCKSEL7	4074h	[2:0]	00h	00h	00h

Data rate: 891Mbps / lane

Register	Register details		Initial value	INCK		
	Address	bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	05h	05h	05h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00C6h	00C0h	00C0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	00h	00h	00h
INCKSEL7	4074h	[2:0]	00h	01h	01h	01h

Data rate: 720Mbps / lane

Register	Register details		Initial value	INCK	
	Address	bit		24 [MHz]	72 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	54h	F8h
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	3Bh	B0h
SYS_MODE	3034h	[7:0]	04h	09h	09h
INCKSEL1	3115h	[7:0]	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	00B4h	00A0h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00FCh	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	0600h	1200h
INCKSEL6	400Ch	[0]	01h	00h	00h
INCKSEL7	4074h	[2:0]	00h	01h	01h

Data rate: 594Mbps / lane

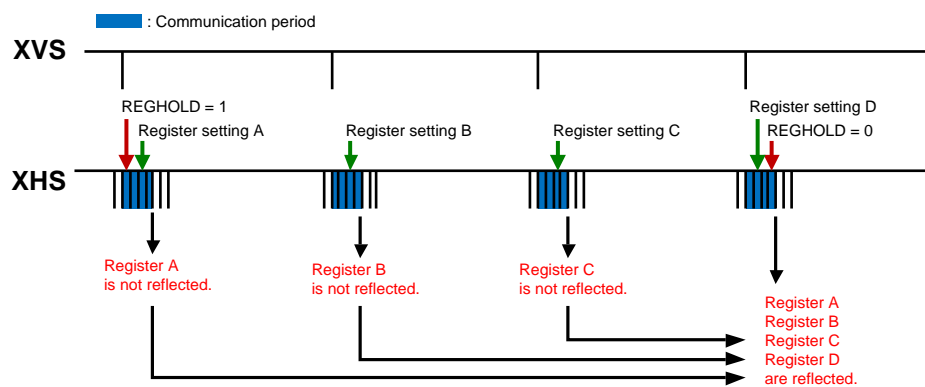
Register	Register details		Initial value	INCK		
	Address	bit		27 [MHz]	37.125 [MHz]	74.25 [MHz]
BCWAIT_TIME	3009-08h	[9:0]	0FFh	05Dh	07Fh	0FFh
CPWAIT_TIME	300B-0Ah	[9:0]	0B6h	042h	05Bh	0B6h
SYS_MODE	3034h	[7:0]	04h	07h	07h	07h
INCKSEL1	3115h	[7:0]	00h	00h	00h	00h
INCKSEL2	3116h	[7:0]	28h	23h	24h	28h
INCKSEL3	3119-18h	[10:0]	00C0h	0084h	0080h	0080h
INCKSEL4	311B-1Ah	[11:0]	00E0h	00E7h	00E0h	00E0h
INCKSEL5	311Eh	[3:0]	28h	23h	24h	28h
TXCLKESC_FREQ	4005-04h	[15:0]	1290h	06C0h	0948h	1290h
INCKSEL6	400Ch	[0]	01h	00h	00h	00h
INCKSEL7	4074h	[2:0]	00h	01h	01h	01h

Register Hold Setting

Register setting can be transmitted with divided to several frames and it can be reflected globally at a certain frame by the register REGHOLD. Setting REGHOLD = 1 at the start of register communication period prevents the registers that are set thereafter from reflecting at the frame reflection timing. The registers that are set when setting REGHOLD = 1 are reflected globally by setting REGHOLD = 0 at the end of communication period of the desired frame to reflect the register.

Register Hold Setting Register

Register	Register details		Initial value	Setting value
	Address	bit		
REGHOLD	3001h	[0]	0h	0: Invalid 1: Valid (Register hold)



Register Hold Setting

Mode Transitions

The Mode transition between operations is shown below. These examples shown in case that setting is completed within one communication timing.

List of Mode Transition

Transition			State
Horizontal direction normal	→	Horizontal direction inverted	Via the Standby state is unnecessary.
Horizontal direction inverted	→	Horizontal direction normal	
All-pixel scan mode	→	Window cropping mode	Via the Standby state is unnecessary. One invalid frame is generated.
Window cropping mode	→	All-pixel scan mode	
Vertical direction normal	→	Vertical direction inverted	
Vertical direction inverted	→	Vertical direction normal	
Vertical direction line number change (Master mode : VMAX change, Slave mode : XVS interval change)			
Horizontal direction 1H period change (Master mode : HMAX change, Slave mode : XHS interval change)			
- Transition between modes other than above - Change the input frequency of INCK ^{*1} - Change the register setting noted "S" in the reflection timing column of the Register Map.			Via the standby state is necessary.

^{*1} When changing input INCK frequency, care should be taken not to be input pulses whose width are shorter than the High / Low level width in front and behind of the INCK pulse at the frequency change. If the pulses above generate at the frequency change, change INCK frequency during system reset in the state of XCLR = Low, and then perform system clear in the state of XCLR = High following the item of "Power on sequence" in the section of "Power on / off sequence". Execute initial setting again because the register settings become default state after system clear.

Other Function

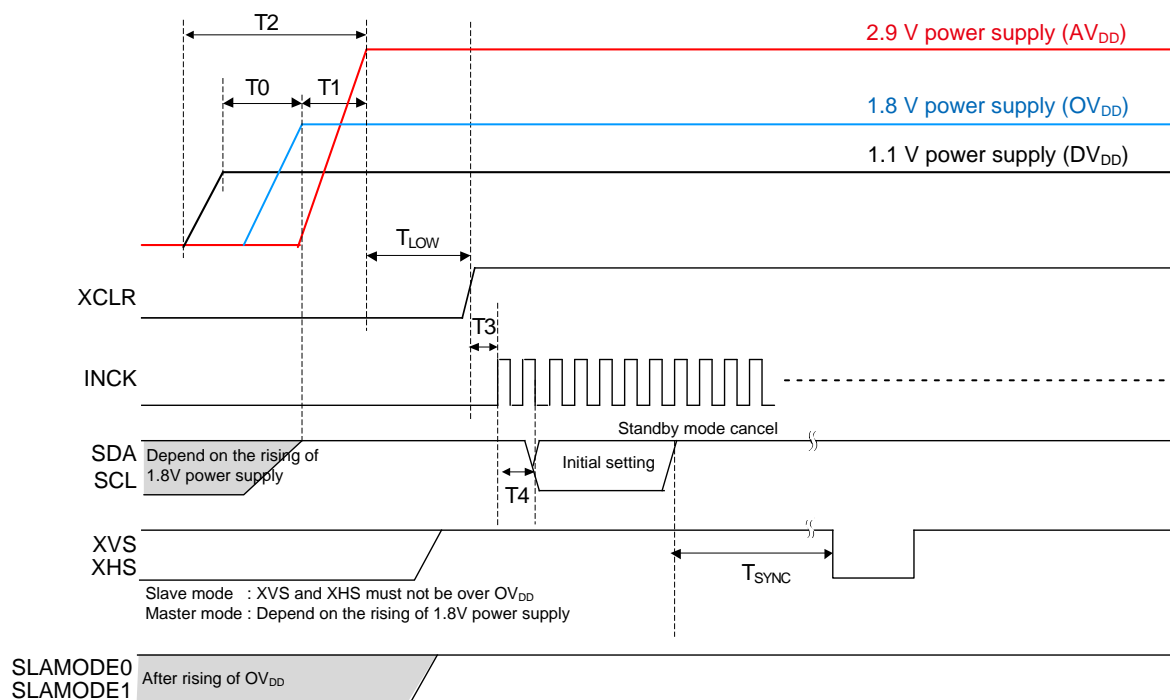
This sensor has the function as below. About detail, refer to each application note.

- Digital overlap HDR (2 / 3 frame)
- Multiple exposure HDR (2 / 4 frame)
- Additional Function of Synchronizing Sensors

Power-on and Power-off Sequence

Power-on sequence

1. Turn On the power supplies so that the power supplies rise in order of 1.1 V power supply (DV_{DD}) → 1.8 V power supply (OV_{DD}) → 2.9 V power supply (AV_{DD}). In addition, all power supplies should finish rising within 200 ms.
2. The register values are undefined immediately after power-on, so the system must be cleared. Hold XCLR at Low level for 500 ns or more after all the power supplies have finished rising. (The register values after a system clear are the default values.)
3. The system clear is applied by setting XCLR to High level. The maser clock input after setting the XCLR pin to High level.
4. Make the sensor setting by register communication after the system clear.

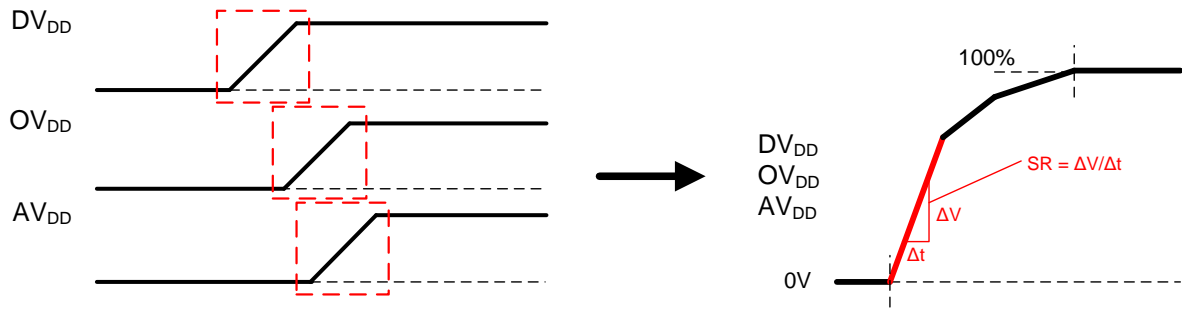


Power-on Sequence

Item	Symbol	Min.	Max.	Unit
1.1 V power supply rising → 1.8 V power supply rising	T0	0	—	ns
1.8 V power supply rising → 2.9 V power supply rising	T1	0	—	ns
Rising time of all power supply	T2	—	200	ms
2.9 V power supply rising → Clear OFF	T _{LOW}	500	—	ns
Clear OFF → INCK rising	T3	1	—	μs
Clear OFF → Communication start	T4	20	—	μs
Standby OFF (communication) → External input XHS, XVS (slave mode only)	T _{SYNC}	24 (TBD)	—	ms

Slew Rate Limitation of Power-on Sequence

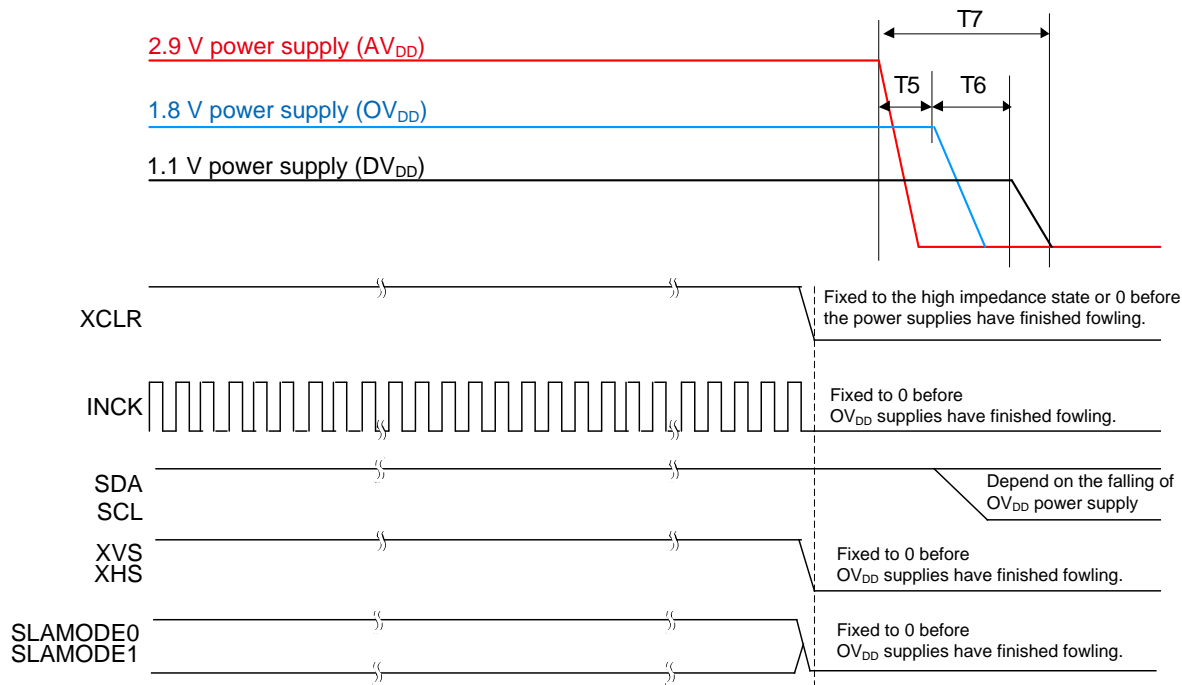
Conform the slew rate limitation shown below when power supply change 0 V to each voltage (0 % to 100 %) in power-on sequence.



Item	Symbol	Power supply	Min.	Max.	Unit	Remarks
Slew rate	SR	DV _{DD} (1.1 V)	—	25	mV/μs	
		OV _{DD} (1.8 V)	—	25	mV/μs	
		AV _{DD} (2.9 V)	—	25	mV/μs	

Power-off sequence

Turn Off the power supplies so that the power supplies fall in order of 2.9 V power supply (AV_{DD}) → 1.8 V power supply (OV_{DD}) → 1.1 V power supply (DV_{DD}). In addition, all power supplies should falling within 200 ms. Set each digital input pin (INCK, SDA, SCL, XCLR, XVS, XHS) to 0 V before the 1.8 V power supply (OV_{DD}) falls.



Power-off Sequence

Item	Symbol	Min.	Max.	Unit
2.9 V power shut down → 1.8 V power shut down	T5	0	—	ns
1.8 V power shut down → 1.1 V power shut down	T6	0	—	ns
Shut down time of all power supply	T7	—	200	ms

Sensor Setting Flow

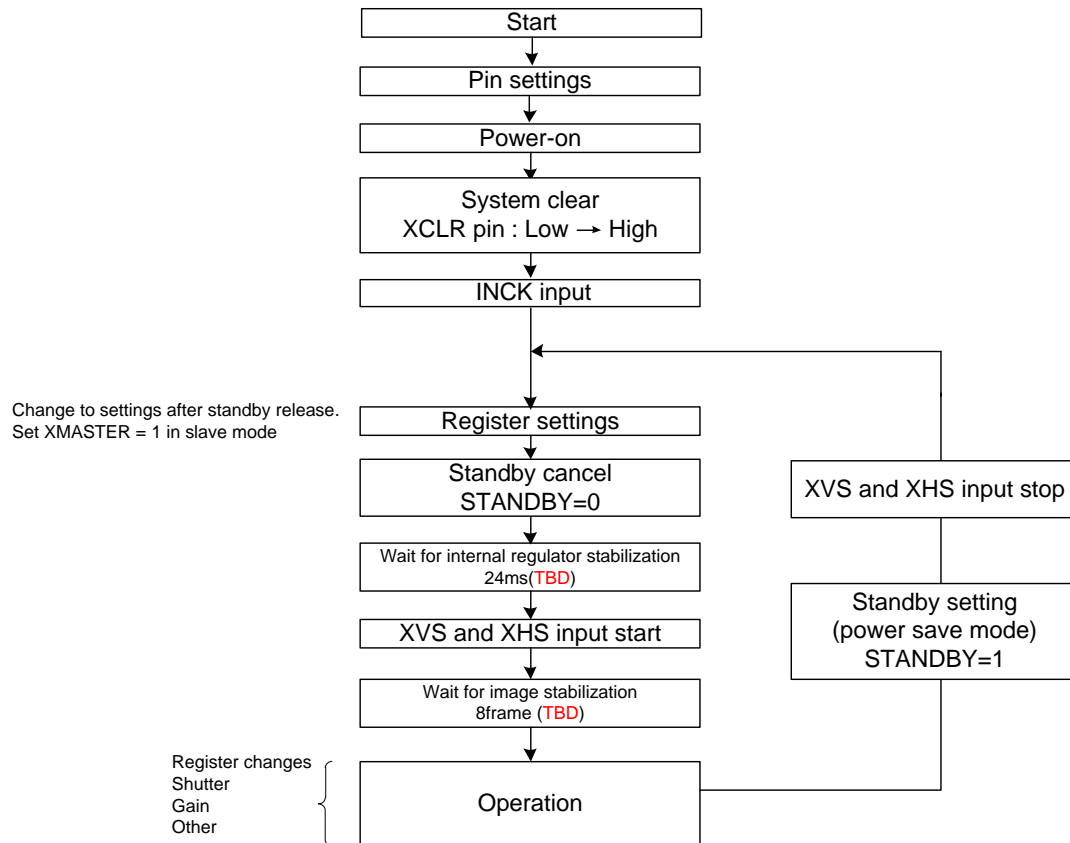
Setting Flow in Sensor Slave Mode

The figure below shows operating flow in sensor slave mode.

For details of "Power-on" to "Reset cancel", see the item of "Power-on sequence" in this section.

For details of "Standby cancel" until "Wait for image stabilization", see the item of "Standby mode".

"Standby setting (power save mode) can be made by setting the STANDBY register to "1" during "Operation".



Sensor Setting Flow (Sensor Slave Mode)

Setting Flow in Sensor Master Mode

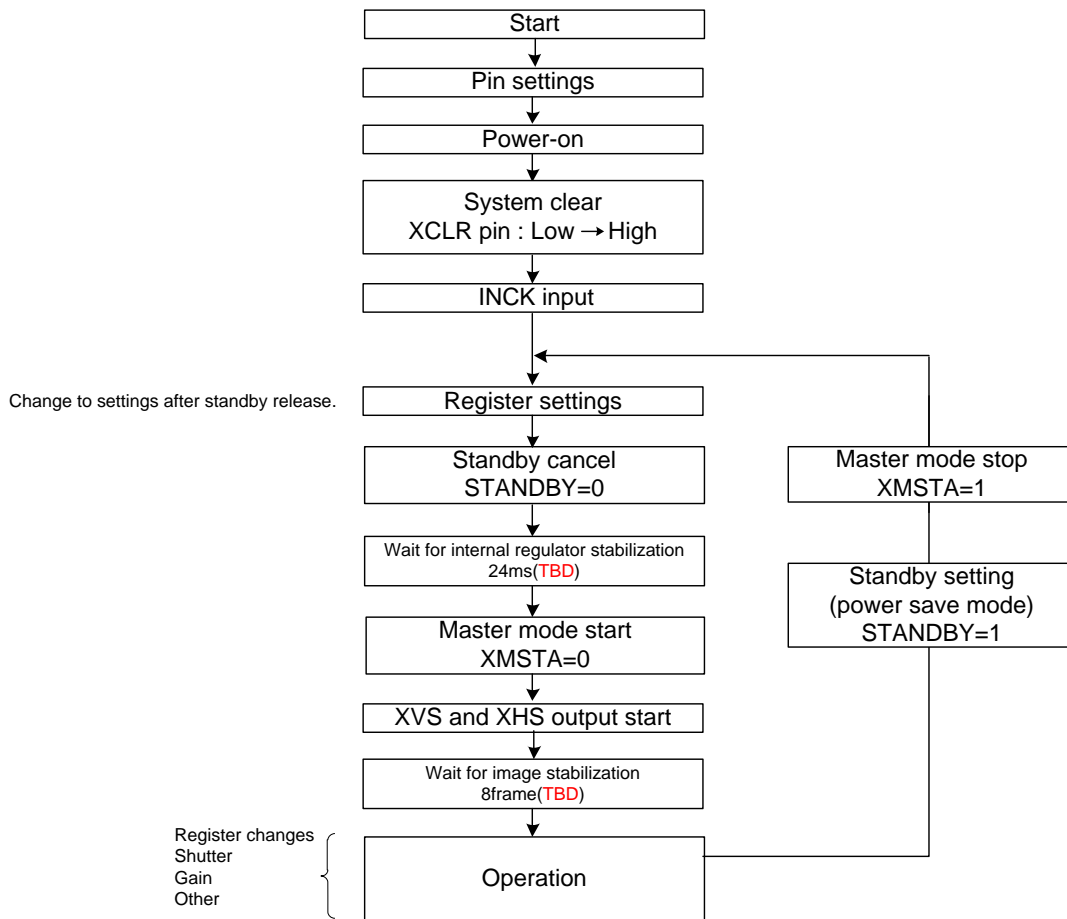
The figure below shows operating flow in sensor master mode.

For details of "Power-on" to "Reset cancel", see the item of "Power on sequence" in this section.

For details of "Standby cancel" until "Wait for image stabilization", see the item of "Standby mode".

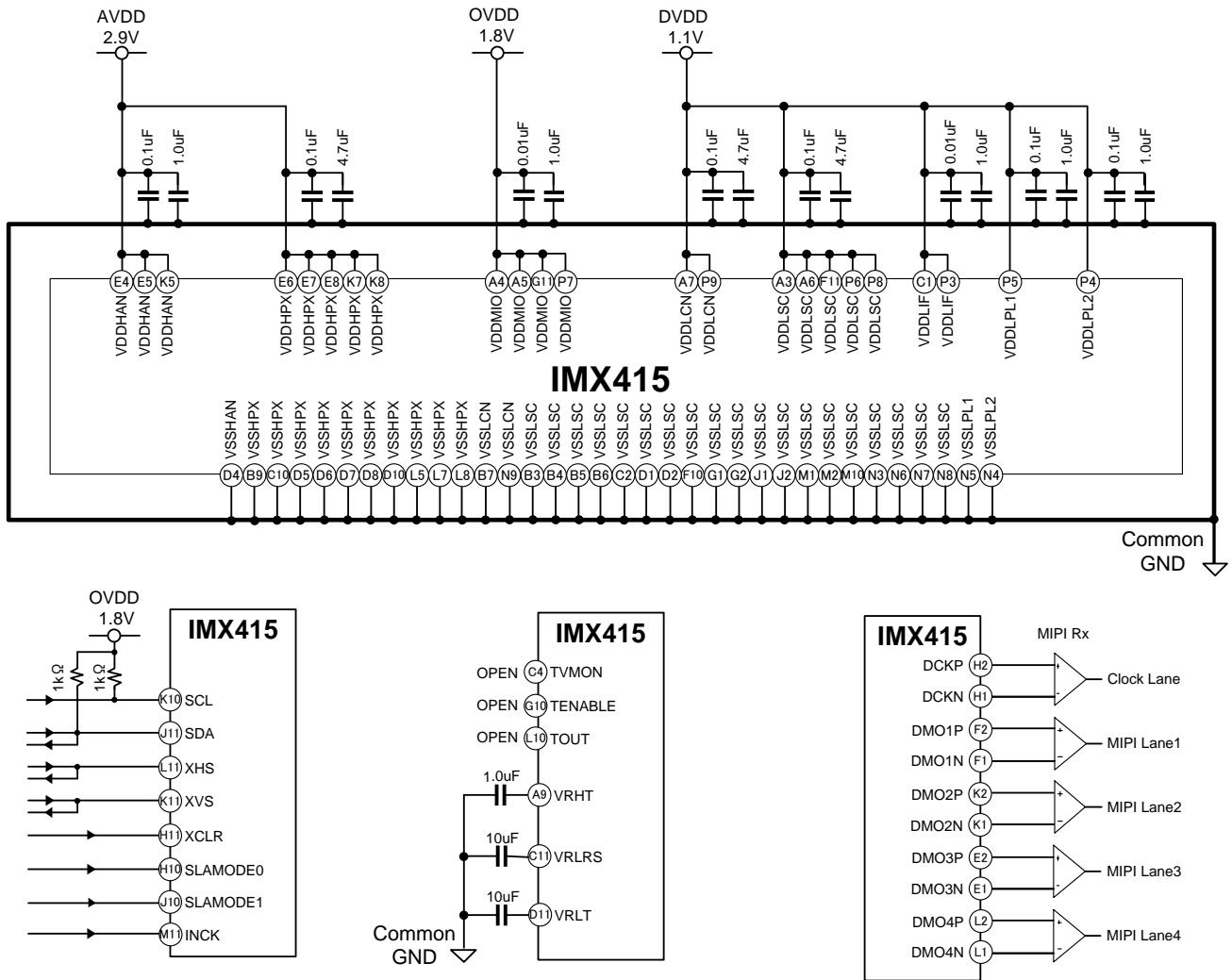
In master mode, "Master mode start" by setting register XMSTA to "0" after "Waiting for internal regulator stabilization"

"Standby setting (power save mode) can be made by setting the STANDBY register to "1" during "Operation". This time, set "master mode stop" by setting XMSTA to "1".



Sensor Setting Flow (Sensor Master Mode)

Peripheral Circuit



Application circuits shown are typical examples illustrating the operation of the devices.
 Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

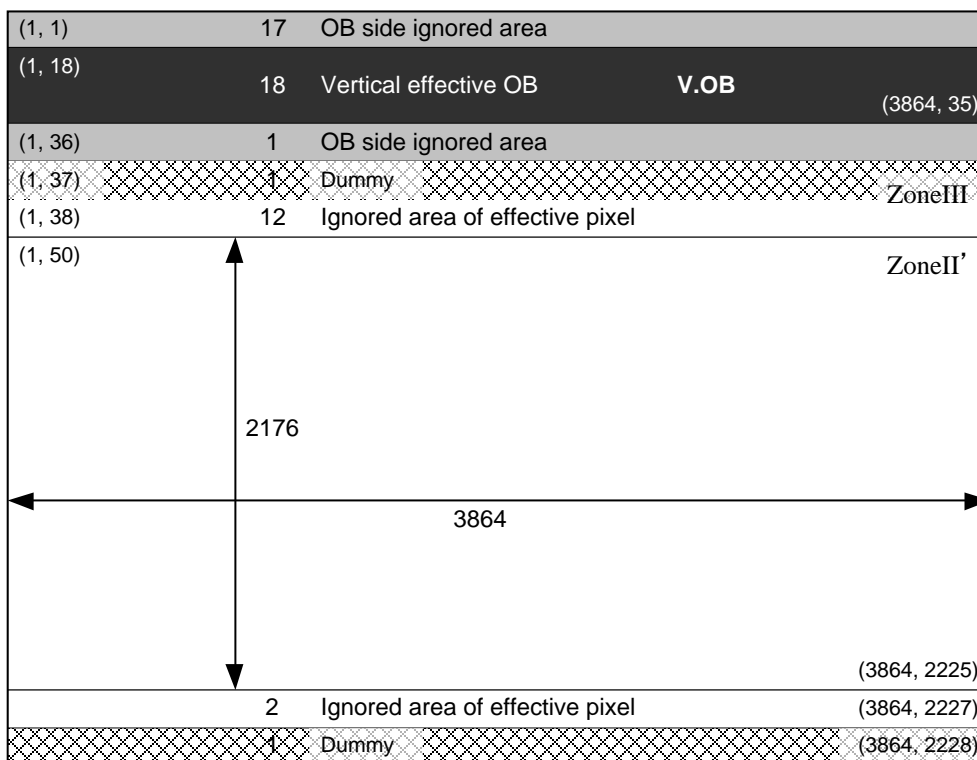
Spot Pixel Specifications

(AV_{DD} = 2.9 V, OV_{DD} = 1.8 V, DV_{DD} = 1.1 V, T_j = 60 °C, 30 frame/s, Gain: 0 dB)

Type of distortion	Level	Maximum distorted pixels in each zone				Measurement method	Remarks
		II'	Effective OB	III	Ineffective OB		
Black or white pixels at high light	TBD % ≤ D	TBD	No evaluation criteria applied		1		
White pixels in the dark	TBD mV ≤ D	TBD		No evaluation criteria applied	2	1/30 s storage	
Black pixels at signal saturated	D ≤ TBD mV	TBD	No evaluation criteria applied		3		

- Note) 1. Zone is specified based on all-pixel drive mode
 2. D Spot pixel level
 3. See the Spot Pixel Pattern Specifications for the specifications in which pixel and black pixel are close.

Zone Definition



Notice on White Pixels Specifications

After delivery inspection of CMOS image sensors, particle radiation such as cosmic rays etc. may distort pixels of CMOS image sensors, and then distorted pixels may cause white point effects in dark signals in picture images. (Such white point effects shall be hereinafter referred to as "White Pixels".)

Unfortunately, it is not possible with current scientific technology for CMOS image sensors to prevent such White Pixels. It is recommended that when you use CMOS image sensors, you should consider taking measures against such White Pixels, such as adoption of automatic compensation systems for White Pixels in dark signals and establishment of quality assurance standards.

Unless the Seller's liability for White Pixels is otherwise set forth in an agreement between you and the Seller, Sony Semiconductor Solutions Corporation or its distributors (hereinafter collectively referred to as the "Seller") will, at the Seller's expense, replace such CMOS image sensors, in the event the CMOS image sensors delivered by the Seller are found to be to the Seller's satisfaction, to have over the allowable range of White Pixels as set forth above under the heading "Spot Pixels Specifications", within the period of three months after the delivery date of such CMOS image sensors from the Seller to you; provided that the Seller disclaims and will not assume any liability after you have incorporated such CMOS image sensors into other products.

Please be aware that Seller disclaims and will not assume any liability for (1) CMOS image sensors fabricated, altered or modified after delivery to you, (2) CMOS image sensors incorporated into other products, (3) CMOS image sensors shipped to a third party in any form whatsoever, or (4) CMOS image sensors delivered to you over three months ago. Except the above mentioned replacement by Seller, neither Sony Semiconductor Solutions Corporation nor its distributors will assume any liability for White Pixels. Please resolve any problem or trouble arising from or in connection with White Pixels at your costs and expenses.

[For Your Reference] The Annual Number of White Pixels Occurrence

The chart below shows the predictable data on the annual number of White Pixels occurrence in a single-story building in Tokyo at an altitude of 0 meters. It is recommended that you should consider taking measures against the annual White Pixels, such as adoption of automatic compensation systems appropriate for each annual number of White Pixels occurrence.

The data in the chart is based on records of past field tests, and signifies estimated number of White Pixels calculated according to structures and electrical properties of each device. Moreover, the data in the chart is for your reference purpose only, and is not to be used as part of any CMOS image sensor specifications.

Example of Annual Number of Occurrence

White Pixel Level (in case of integration time = 1/30 s) (Tj = 60 °C)	Annual number of occurrence
5.6 mV or higher	TBD pcs
10.0 mV or higher	TBD pcs
24.0 mV or higher	TBD pcs
50.0 mV or higher	TBD pcs
72.0 mV or higher	TBD pcs

Note 1) The above data indicates the number of White Pixels occurrence when a CMOS image sensor is left for a year.

Note 2) The annual number of White Pixels occurrence fluctuates depending on the CMOS image sensor storage environment (such as altitude, geomagnetic latitude and building structure), time (solar activity effects) and so on. Moreover, there may be statistic errors. Please take notice and understand that this is an example of test data with experiments that have being conducted over a specific time period and in a specific environment.

Note 3) This data does not guarantee the upper limits of the number of White Pixels occurrence.

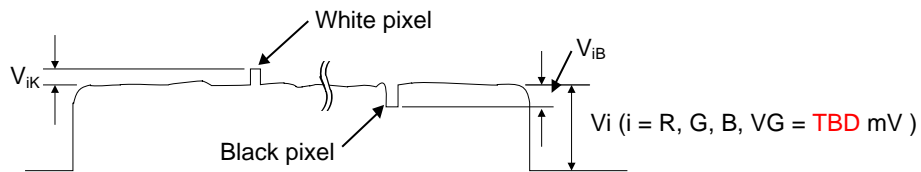
Measurement Method for Spot Pixels

After setting to standard imaging condition II, and the device driver should be set to meet bias and clock voltage conditions. Configure the drive circuit according to the example and measure.

1. Black or white pixels at high light

After adjusting the luminous intensity so that the average value V_G of the Gb / Gr signal outputs is **TBD** mV, measure the local dip point (black pixel at high light, V_{iB}) and peak point (white pixel at high light, V_{iK}) in the Gr / Gb / R / B signal output V_i ($i = Gr / Gb / R / B$), and substitute the value into the following formula.

$$\text{Spot pixel level } D = ((V_{iB} \text{ or } V_{iK}) / \text{Average value of } V_i) \times 100 \text{ [\%]}$$



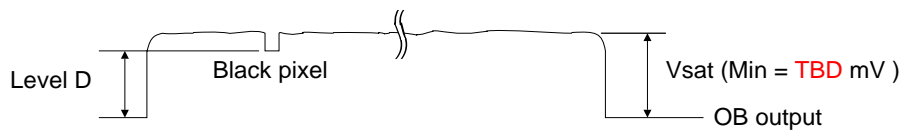
Signal output waveform of R / G / B channel

2. White pixels in the dark

Set the device to a dark setting and measure the local peak point of the signal output waveform, using the average value of the dark signal output as a reference.

3. Black pixels at signal saturated

Set the device to operate in saturation and measure the local dip point, using the OB output as a reference.


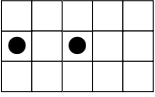
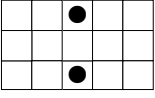


Signal output waveform of R/G/B channel

Spot Pixel Pattern Specification

White Pixel, Black Pixel and Bright Pixel are Kudded from the pattern whether they are allowed or reKected, and counted.

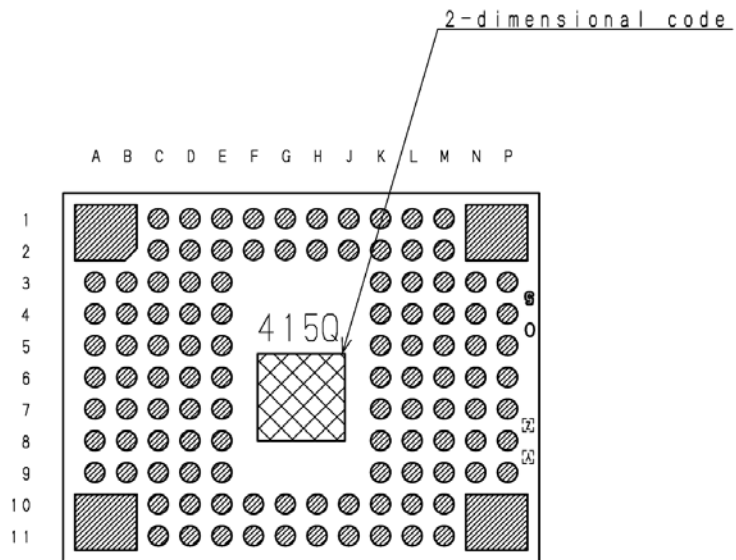
List of White Pixel, Black Pixel and Bright Pixel Pattern

No.	Pattern 	White pixel Black pixel Bright pixel
1		Rejected
2		Rejected

- Note) 1. "●" shows the position of white pixel, black pixel and bright pixel.
 White pixel, black pixel and bright pixel are specified separately according the pattern.
 (Example: If a black pixel and a white pixel is in the pattern No.1 respectively, they are not Kudded to be reKected.)
- When one or more spot pixels indicated "ReKected" is selected and removed.
 - Spot pixels other than described in the table above are all counted including the number of allowable spot pixels by zone.

Marking

(Tentative)



Y: In English upper case character, One character
 Z: Number, single number

DRAWING No. AM-*415AAQR (2D)

Notes On Handling

1. Static charge prevention

Image sensors are easily damaged by static discharge. Before handling be sure to take the following protective measures.

- (1) Either handle bare handed or use non-chargeable gloves, clothes or material.
Also use conductive shoes.
- (2) Use a wrist strap when handling directly.
- (3) Install grounded conductive mats on the floor and working table to prevent the generation of static electricity.
- (4) Ionized air is recommended for discharge when handling image sensors.
- (5) For the shipment of mounted boards, use boxes treated for the prevention of static charges.

2. Protection from dust and dirt

Image sensors are packed and delivered with care taken to protect the element glass surfaces from harmful dust and dirt. Clean glass surfaces with the following operations as required before use.

- (1) Perform all lens assembly and other work in a clean environment (class 1000 or less).
- (2) Do not touch the glass surface with hand and make any object contact with it.
If dust or other is stuck to a glass surface, blow it off with an air blower.
(For dust stuck through static electricity, ionized air is recommended.)
- (3) Clean with a cotton swab with ethyl alcohol if grease stained. Be careful not to scratch the glass.
- (4) Keep in a dedicated case to protect from dust and dirt. To prevent dew condensation, preheat or precool when moving to a room with great temperature differences.
- (5) When a protective tape is applied before shipping, remove the tape applied for electrostatic protection just before use. Do not reuse the tape.

3. Installing (attaching)

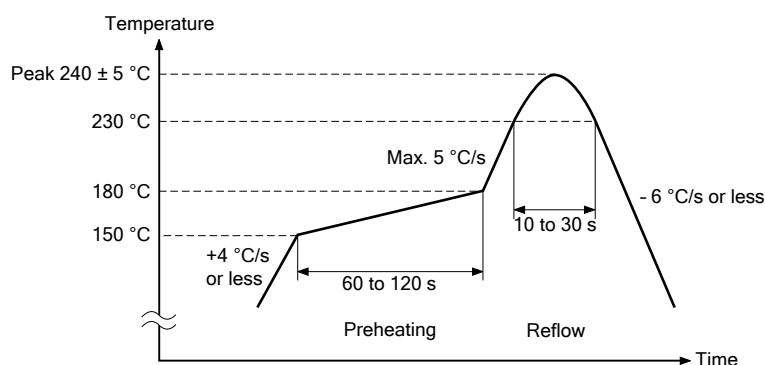
- (1) If a load is applied to the entire surface by a hard component, bending stress may be generated and the package may fracture, etc., depending on the flatness of the bottom of the package.
Therefore, for installation, use either an elastic load, such as a spring plate, or an adhesive.
- (2) The adhesive may cause the marking on the rear surface to disappear.
- (3) If metal, etc., clash or rub against the package surface, the package may chip or fragment and generate dust.
- (4) Acrylate anaerobic adhesives are generally used to attach this product. In addition, cyanoacrylate instantaneous adhesives are sometimes used jointly with acrylate anaerobic adhesives to hold the product in place until the adhesive completely hardens. (Reference)
- (5) Note that the sensor may be damaged when using ultraviolet ray and infrared laser for mounting it.

4. Recommended reflow soldering conditions

The following items should be observed for reflow soldering.

(1) Temperature profile for reflow soldering

Control item	Profile (at part side surface)
1. Preheating	150 to 180 °C 60 to 120 s
2. Temperature up (down)	+4 °C/s or less (- 6 °C/s or less)
3. Reflow temperature	Over 230 °C 10 to 30 s Max. 5 °C/s
4. Peak temperature	Max. 240 ± 5 °C



(2) Reflow conditions

- Make sure the temperature of the upper surface of the seal glass resin adhesive portion of the package does not exceed 245 °C.
- Perform the reflow soldering only one time.
- Finish reflow soldering within 72 h after unsealing the degassed packing.
Store the products under the condition of temperature of 30 °C or less and humidity of 70 % RH or less after unsealing the package.
- Perform re-baking only one time under the condition at 125 °C for 24 h.
- Note that condensation on glass or discoloration on resin interfaces may occur if the actual temperature and time exceed the conditions mentioned above.

(3) Others

- Carry out evaluation for the solder joint reliability in your company.
- After the reflow, the paste residue of protective tape may remain around the seal glass.
(The paste residue of protective tape should be ignored except remarkable one.)
- Note that X-ray inspection may damage characteristics of the sensor.

5. Others

- Do not expose to strong light (sun rays) for long periods, as the color filters of color devices will be discolored.
- Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or use in such conditions.
- This product is precision optical parts, so care should be taken not to apply excessive mechanical shocks or force.
- Note that imaging characteristics of the sensor may be affected when approaching strong electromagnetic wave or magnetic field during operation.
- Note that image may be affected by the light leaked to optical black when using an infrared cut filter that has transparency in near infrared ray area during shooting subjects with high luminance.

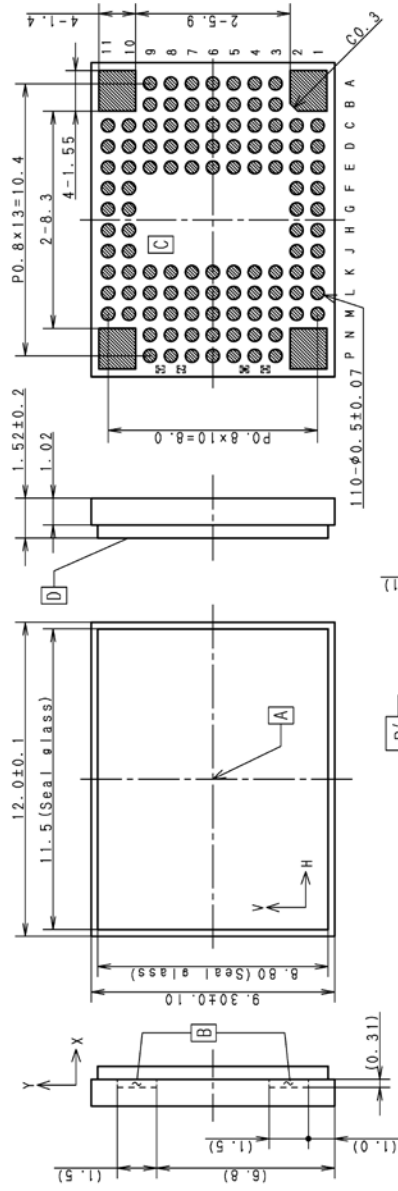
Material_No.14-0.0.8

Package Outline

(Unit: mm)

TENTATIVE

114Pin-LGA



- 1) "A" is the center of the effective image area
- 2) The two points "G" of the package are the horizontal reference
- 3) The point "G" of the package is the vertical reference
- 4) The bottom "C" of the package is the height reference
- 5) Base level "S" is a virtual flat surface calculated at three points (A11, P1, P11) of back side terminal
- 6) The center of the effective image area relative to "B", "G", and "G'" is (H, V) = (6.00, 4.65)±0.075mm
- 7) The rotation angle of the effective image area relative to "H", "G", and "V" is ±1.1°
- 8) The height from the bottom "C" to the effective image area is 0.62±0.10 mm
- 9) The height from the top of cover glass "D" to the effective image area is 0.90±0.15 mm is less than 0.05 mm
- 10) The tilt of the effective image area relative to the bottom "C" of the cover glass is less than 0.05mm
- 11) The thickness of the cover glass is 0.5 mm, and the refractive index is 1.5
- 12) As for standard for resin overflow in package outside, the resin overflow is not allowed in package
- 13) One character of alphabet or number shall be placed from W to Z part.
- 14) (Plating permission)
- 15) General tolerance ±0.2mm

PACKAGE STRUCTURE	
PACKAGE MATERIAL	Ceramic
LEAD TREATMENT	GOLD PLATING
PACKAGE HEIGHT	0.5±
DRAWING NUMBER	AS-K415(E)

List of Trademark Logos and Definition Statements

STARVIS

* STARVIS is a trademark of Sony Corporation. The STARVIS is back-illuminated pixel technology used in CMOS image sensors for surveillance camera applications. It features a sensitivity of 2000 mV or more per $1 \mu\text{m}^2$ (color product, when imaging with a 706 cd/m^2 light source, F5.6 in 1 s accumulation equivalent), and realizes high picture quality in the visible-light and near infrared light regions.

Revision History

Date of change	Ver	Page	Contain of Change
2018/08/09	0.1	—	First Edition